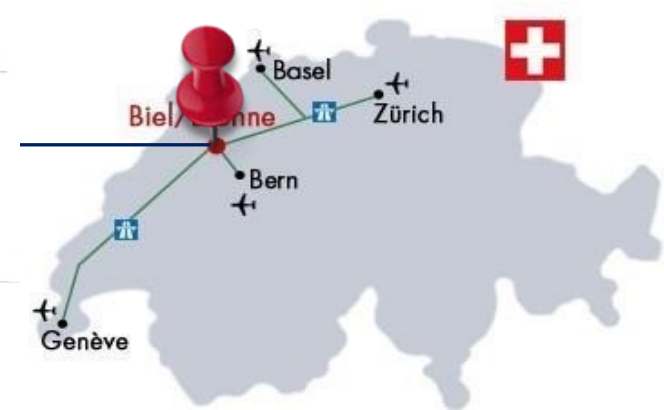

posalux[®]

SWISS MADE 



08th of February 2017

Posalux SA - Switzerland



Founded in 1943, Posalux is a leading Suisse manufacturer for micro technologies for mass production.

Posalux is headquartered in Biel-Bienne, one of the most important cities of Switzerland, which is famous not only as a watch metropolis, but also as one of the most important centers for advanced and micro technologies.

Global presences:

- Subsidiaries of Posalux in Germany, Korea and Taiwan
- Worldwide network of sales and service agents in major countries

Posalux – Business Strategy

Best in class **system solution provider** to enhance and grow our customers business and become supplier of choice with mutual benefit and success

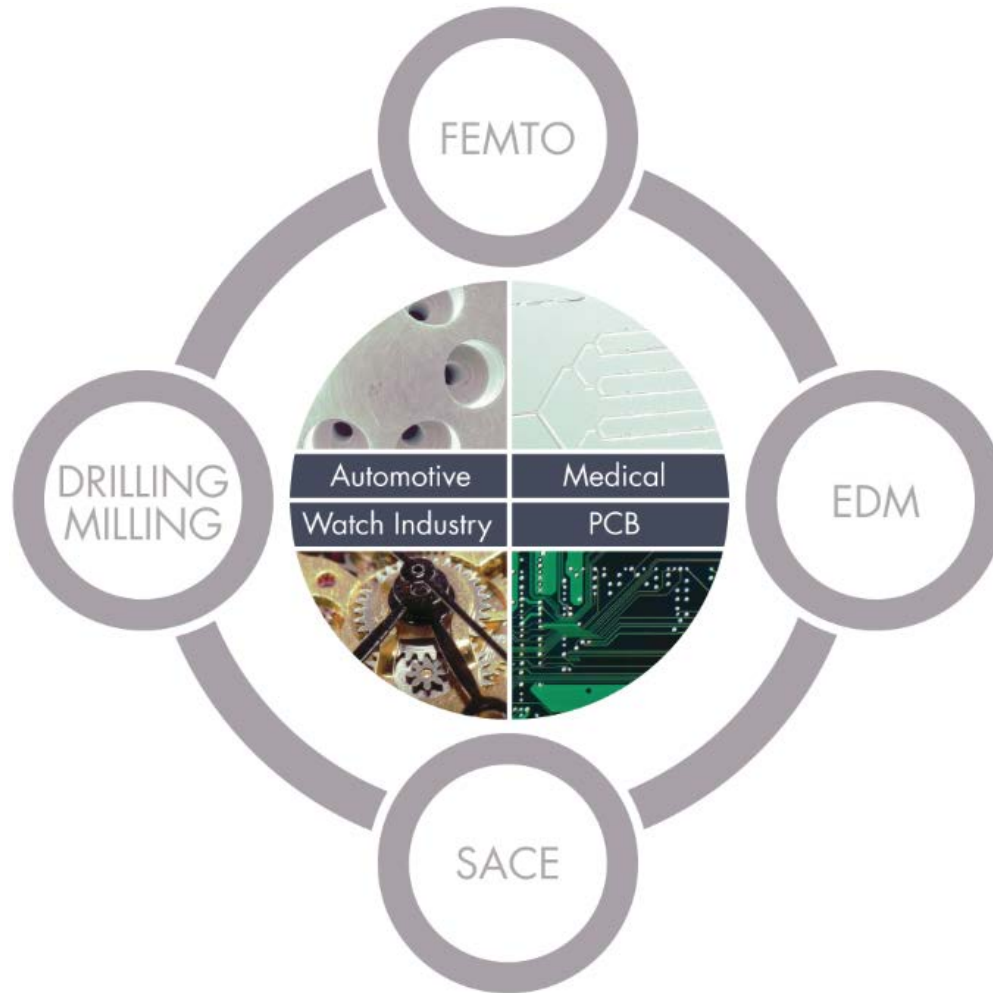
Development and industrialization of standardized high-technology machines for mass production in niche markets

Fulfill and exceed our **customers expectations**, internal & external

Attract, develop and retain highly talented people to ensure **long-term success** for Posalux

Foster national and **international collaborations with Universities** and Universities of applied sciences to increase the speed of innovation

Four technology families for four markets





Posalux Core Competencies

Joint development of future applications with our customers,
to meet and exceed product-process specifications

Supply of highly accurate and productive equipment,
95% for export worldwide

We provide **complete solutions** – not only machine tools

Application knowledge and **process support** for our customers

Worldwide Service - active and very efficient worldwide

Excellent knowledge of our **worldwide markets**



Posalux Customers

Major customers are Automotive and Electronics with strong requirements. E.G. to reach final goals: PPM 0km < 2 and vehicles warranties from 2 to 7 years

Quality first : $Cpk > 1,67$ / $Cp > 2,0$

FMEA process mandatory with customers, final concept and design validated in common with Posalux and customers

Common building for maintenance plans and setting

Posalux warranty from 18 to 24 months, service reactivity max 24h

Quality dossier, with measurements report by Posalux, arrived from customer equivalent or better devices

Individual traceability or post process devices integration...

POSALUX - 4 Technologies

μ-Machining

EDM

SACE

Femto-LASER

PCB Micro Drilling and Routing

posalux

Milling machining

posalux

μ-Drilling & Routing

Milling

EDM micro-machining

posalux

μ-Drilling & μ-Milling

Spark Assisted Chemical Engraving

posalux

Drilling, μ-Cutting, μ-Milling & Texturation

LASER Femto

posalux

Femto for μ-Drilling, μ-Cutting & Ablation

POSALUX - 4 Technologies

μ-Machining

EDM

SACE

Femto-LASER



PCB Micro Drilling and Routing

Milling machining

μ-Drilling & Routing

Milling



EDM micro-machining

μ-Drilling & μ-Milling



Spark Assisted Chemical Engraving

Drilling, μ-Cutting, μ-Milling & Texturation



LASER Femto

Femto for μ-Drilling, μ-Cutting & Ablation

2D μ -Drilling and Routing

Specifications

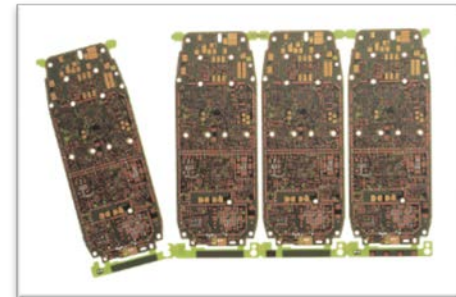
- Hole diameter of 75 microns
- Hit rate: 1'200 hit/min/spindle
- Accuracy ± 25 microns
- Axes acceleration up to 4g
- Diameter/depth ratio 1/10
- 12 spindles per machine
- 12'000 tools embedded



Applications

Dedicated to non ferrous material

- Printed circuit board (PCB) → epoxy-glass fiber
- Watch industry → brass
- Aerospace industry → aluminum



2D μ -Drilling and Routing

Technology

- High frequency spindle 350'000 rpm
- Full linear motion
- Tool management
- Controlled depth +/- 10 microns
- SPC (Statistical Process Control)
- Tactile and intuitive MMI



Machine configuration

- GA6000: 6 stations, 6 or 12 spindles
- DUO, TRIO: 2 or 3 stations, 2 to 6 spindles
- MONO: 1 station, 1 or 2 spindles

up to 6'000 tools
up to 4'200 tools
up to 2'000 tools

μ-Drilling-Routing Mono-E

Specifications

- Tool diameter from 100 microns
- Hit rate: up to 484 hit/min/spindle
- Accuracy +/- 4 microns
- Axes acceleration up to 4g
- Diameter/depth ratio 1/10
- 2 spindles per machine
- 2'000 tools embedded



Applications

Dedicated to non ferrous material

- Watch industry → Brass
- Medical → Titanium, Aluminum



High precise Drilling-Routing Mono-E

Technology

- High frequency spindle 200'000 rpm
- High stiffness routing spindle 60'000 rpm
- Full linear motion
- Tool management
- Controlled depth +/- 10 microns
- SPC (Statistical Process Control)
- Tactile and intuitive MMI



Machine configuration

- MONO: 1 station, 2 spindles, up to 2'000 tools
- Automation: individual loader with 8 stacks

POSALUX - 4 Technologies

μ-Machining

EDM

SACE

Femto-LASER



Micro-machining technologies overview. The top section is divided into two panels: 'PCB Micro Drilling and Routing' and 'Milling machining'. The bottom section contains the text 'μ-Drilling & Routing' and 'Milling'.

PCB Micro Drilling and Routing

Milling machining

μ-Drilling & Routing

Milling



EDM micro-machining overview. The top section shows 'EDM micro-machining' with various images of the process. The bottom section contains the text 'μ-Drilling & μ-Milling'.

EDM micro-machining

μ-Drilling & μ-Milling



SACE overview. The top section shows 'Spark Assisted Chemical Engraving' with various images of the process. The bottom section contains the text 'Drilling, μ-Cutting, μ-Milling & Texturation'.

Spark Assisted Chemical Engraving

Drilling, μ-Cutting, μ-Milling & Texturation



Femto-LASER overview. The top section shows 'LASER Femto' with various images of the process. The bottom section contains the text 'Femto for μ-Drilling, μ-Cutting & Ablation'.

LASER Femto

Femto for μ-Drilling, μ-Cutting & Ablation

μ-Milling

Specifications

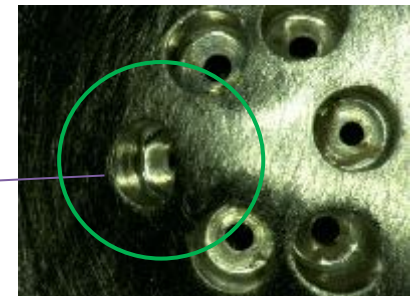
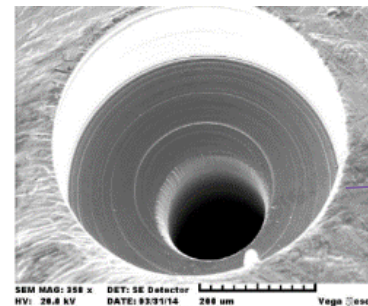
- μ-Milling for hardened material e.g. < 67 HRC, Ø 0.3 - 0.9 mm
- High productivity: 6 step-holes and 2 marks < 11 sec
- Vibration reduction during milling process
- Cutting force optimized
- Tool life optimized > 5'000 holes
- Dedicated to customer application



Applications

Dedicated to hardened ferrous material

- Stainless steel
- Titanium
- Automotive and Medical



μ-Milling

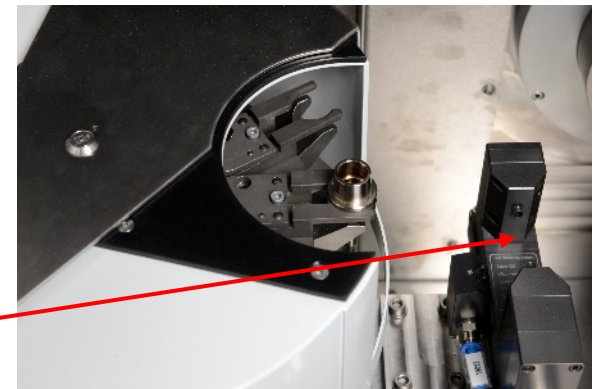
Milling process



Tool magazine
(12 positions)



Tool check @100%
by laser

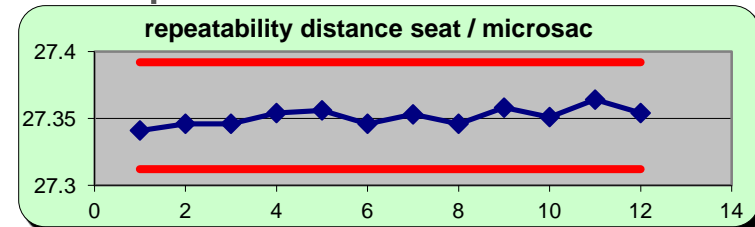
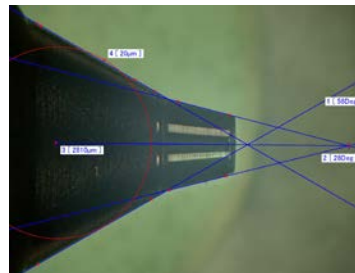
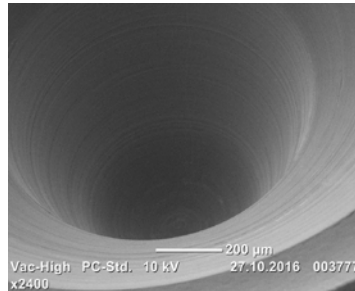
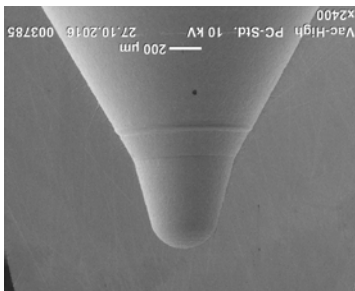


Micro-sac for Nozzle milled after heat-treatment.

Control Sac volume (position + diameter), strong repeatability

Advantages:

- Concentricity between Seat and Sac
- Correction of microsac roundness **after heat-treatment**
- Control microsac volume and no presence of burrs



Tol. distance seat/micro-sac $\pm 20 \mu\text{m}$

Concentricity $< 15 \mu\text{m}$

Roundness $< 5 \mu\text{m}$

Roughness Ra $< 0.37 \mu\text{m}$

POSALUX - 4 Technologies

μ -Machining

EDM

SACE

Femto-LASER



PCB Micro Drilling and Routing

Milling machining

μ -Drilling & Routing

Milling

This block contains two vertical panels. The left panel is titled 'PCB Micro Drilling and Routing' and features a diagram of a drilling process and a photograph of a machine. The right panel is titled 'Milling machining' and features a diagram of a milling process and a photograph of a machine. Below the diagrams, the text ' μ -Drilling & Routing' is written vertically on the left and 'Milling' is written vertically on the right.



EDM micro-machining

μ -Drilling & μ -Milling

This block contains a vertical panel titled 'EDM micro-machining'. It features a diagram of an EDM process and a photograph of a machine. Below the diagram, the text ' μ -Drilling & μ -Milling' is written vertically.



Spark Assisted Chemical Engraving

Drilling, μ -Cutting, μ -Milling & Texturation

This block contains a vertical panel titled 'Spark Assisted Chemical Engraving'. It features a diagram of the SACE process and a photograph of a machine. Below the diagram, the text 'Drilling, μ -Cutting, μ -Milling & Texturation' is written vertically.



LASER Femto

Femto for μ -Drilling, μ -Cutting & Ablation

This block contains a vertical panel titled 'LASER Femto'. It features a diagram of a femto-laser process and a photograph of a machine. Below the diagram, the text 'Femto for μ -Drilling, μ -Cutting & Ablation' is written vertically.

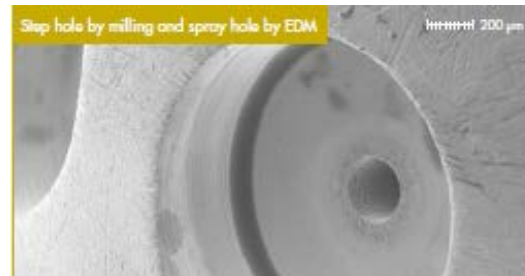
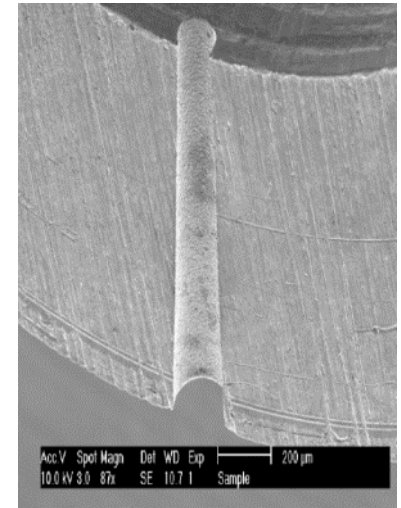
μ-Drilling with EDM

Specifications

- Hole diameter of 50 microns
- Accuracy +/- 3 microns
- Diameter/depth ratio 1/12
- 4 spindles per machine
- Conical hole
- Positive and negative taper
- Blind shapes, step holes



Ø 50 μm



Applications

Dedicated to conductive material

- Automotive industry :
 - Diesel high pressure
 - Gasoline Direct Injection (GDI)

μ-Drilling with EDM

Technology

- Short pulse SARIX generator (80 nano secondes)
- Regulation by average voltage
- 6 axes machine



Machine configuration

- HP4: 1, 2 or 4 spindles
- FP1 – HFP : 1 spindle



- Available options
 - ➔ Automatic load/unload of parts
 - ➔ Flow control
 - ➔ Individual traceability
 - ➔ Camera positioning

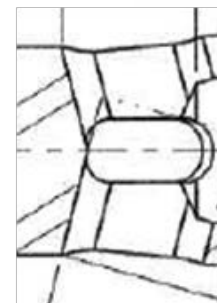
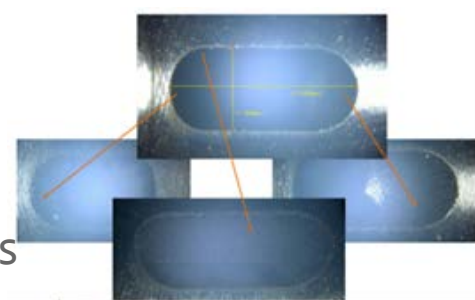
μ -Drilling with EDM

New 2017 serial machines : HP4-EDM V7

- Productivity improvements : more than +30%
- 6 axes machine & 3 axis interpolations
- Tilting head : accuracy increase at 0.1 μm instead of 1
- New generator with low energy : machining small hole with surface finish from Ra 0.3 μm to Ra 0.15 μm
- Integration of a current measurement accuracy for measuring spark lower than 100 ns and lower amperage



HP4
FP1



- 3 axis interpolations

POSALUX - 4 Technologies

μ-Machining

EDM

SACE

Femto-LASER



PCB Micro Drilling and Routing

Milling machining

μ-Drilling & Routing

Milling

This block contains two vertical panels. The left panel is titled 'PCB Micro Drilling and Routing' and features a diagram of a drilling process and a photograph of a PCB. The right panel is titled 'Milling machining' and features a diagram of a milling process and a photograph of a milled part. Below the diagrams, the text 'μ-Drilling & Routing' and 'Milling' is displayed vertically.



EDM micro-machining

μ-Drilling & μ-Milling

This block contains a vertical panel titled 'EDM micro-machining' with a diagram of an EDM process and a photograph of a milled part. Below the diagram, the text 'μ-Drilling & μ-Milling' is displayed vertically.



Spark Assisted Chemical Engraving

Drilling, μ-Cutting, μ-Milling & Texturation

This block contains a vertical panel titled 'Spark Assisted Chemical Engraving' with a diagram of the SACE process and a photograph of a machine. Below the diagram, the text 'Drilling, μ-Cutting, μ-Milling & Texturation' is displayed vertically.



LASER Femto

Femto for μ-Drilling, μ-Cutting & Ablation

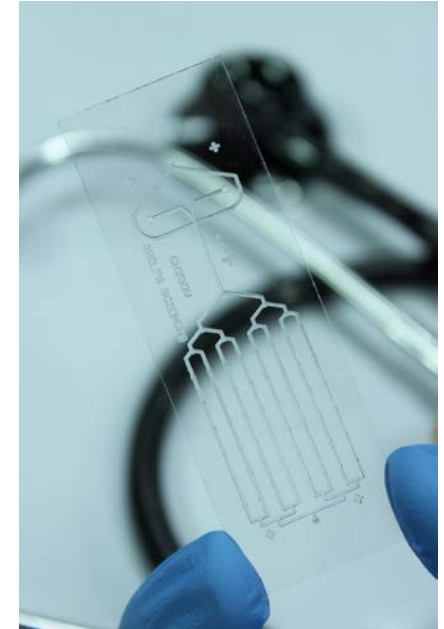
This block contains a vertical panel titled 'LASER Femto' with a diagram of a laser process and a photograph of a machine. Below the diagram, the text 'Femto for μ-Drilling, μ-Cutting & Ablation' is displayed vertically.

Spark Assisted Chemical Engraving

Micromachining of glass (and all materials that contain SiO_2)



Glass, a fantastic material

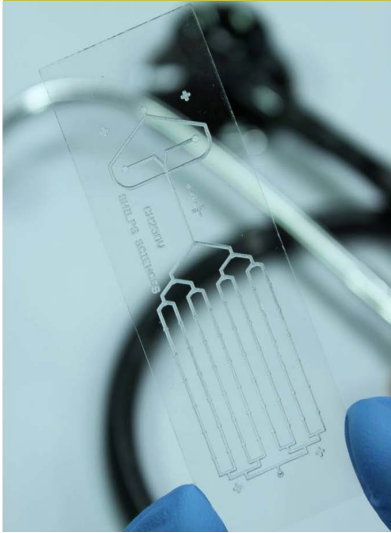


- ✓ Sterilisable
- ✓ Wide optical transparency
- ✓ Impermeable to gases
- ✓ Low thermal expansion
- ✓ Excellent chemical inertness
- ✓ Biocompatible

Nevertheless glass is difficult to machine... until SACE technology introduction

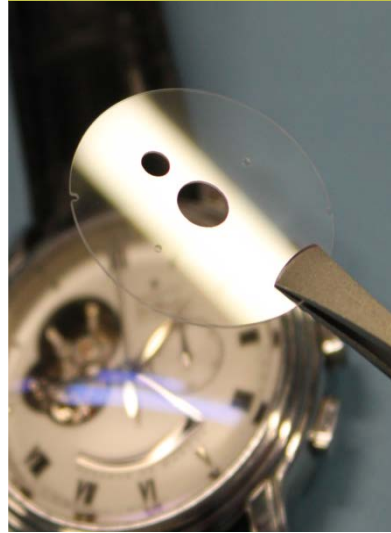
Various applications

Medical



- Medical (Lab-On-Chip)
- Chemical (mixer chips, micro-reactor)
- Multi-layers chips

Watch Industry



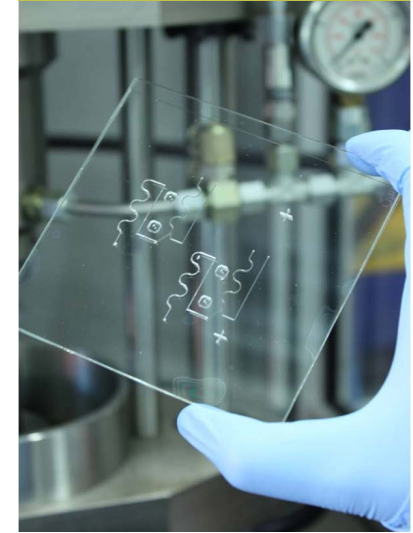
- Watch dial glass
- Mechanical parts
- Process for product anti-counterfeiting marks

Consumer Electronics



- Through Glass Vias (TGV)
- Packaging
- Automatic “stop etch function” when touching conductive layer

Rapid Prototyping



- Industrial R&D
- Fundamental Research
- Surface texturing
- “Batch Size 1”

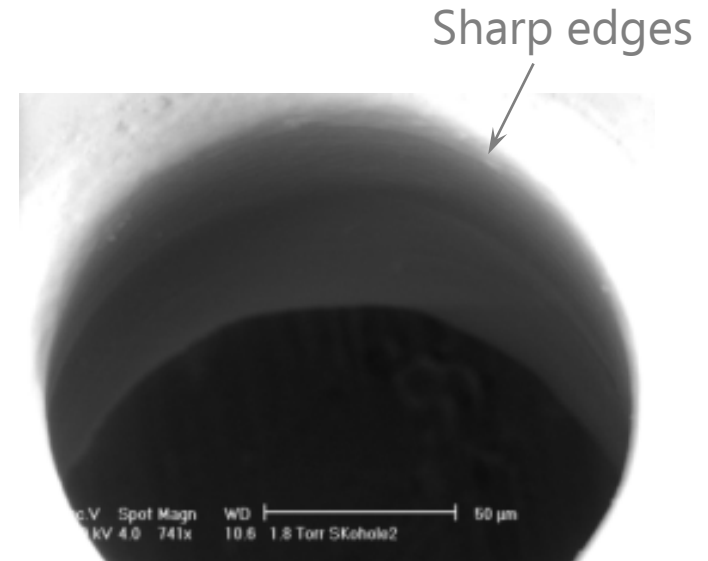
Why the SACE ?

SACE is a solution with:

- ✓ No micro-cracks
- ✓ No burs (easy fusion bonding)
- ✓ No masks needed
- ✓ No highly toxic chemicals, No HF

- ✓ Clean room compatible
- ✓ Flexible technology

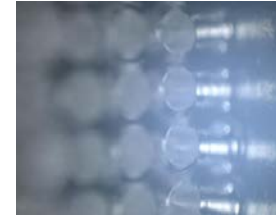
- ✓ And cost effective :
 - Low cost chemical used (NaOH, KOH)
 - Low cost tools (similar to used in PCB)
 - Long life of the tools
 - Low maintenance



Which materials

Glass

Pyrex,
BF33,
D263T,
Mempax,
AF32,
B270,
...



Quartz

Fused silica

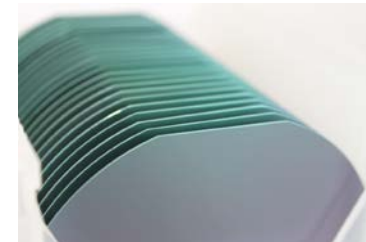


Enamel



Tempered glass

Corning Gorilla,
AGC Dragontrail,
Schott Xensation,
...

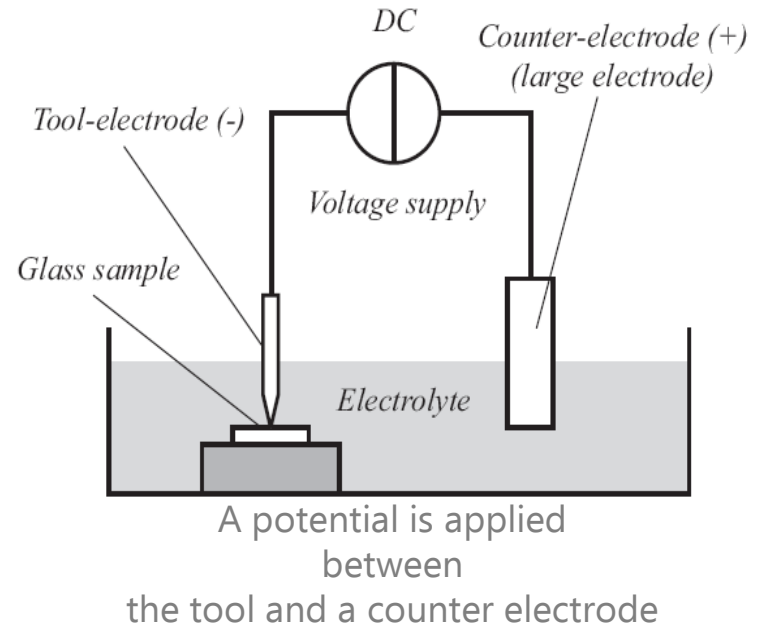
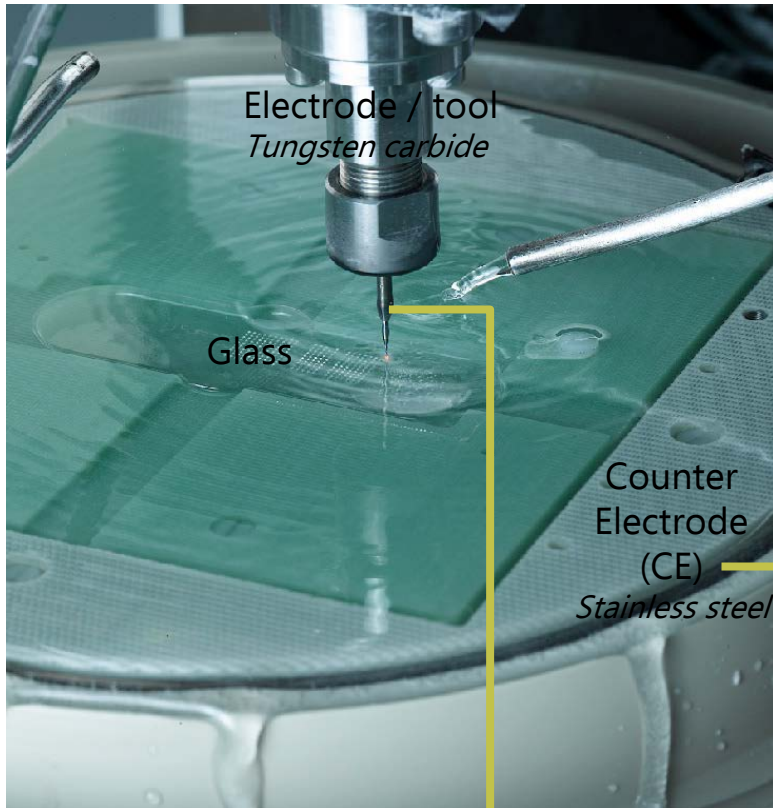


Silicon

All materials
that
contains
 SiO_2

How does the SACE work?

SACE setup



Voltage supply (DC)

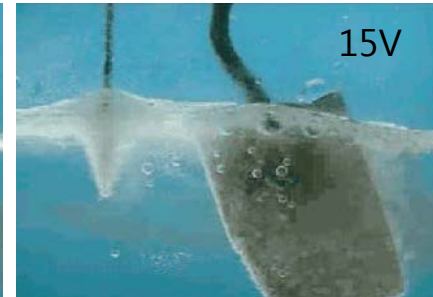
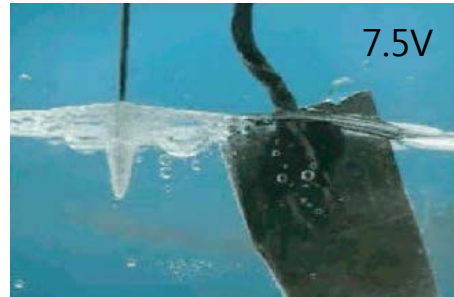


Gas film and spark formation



Potential applied to the tool

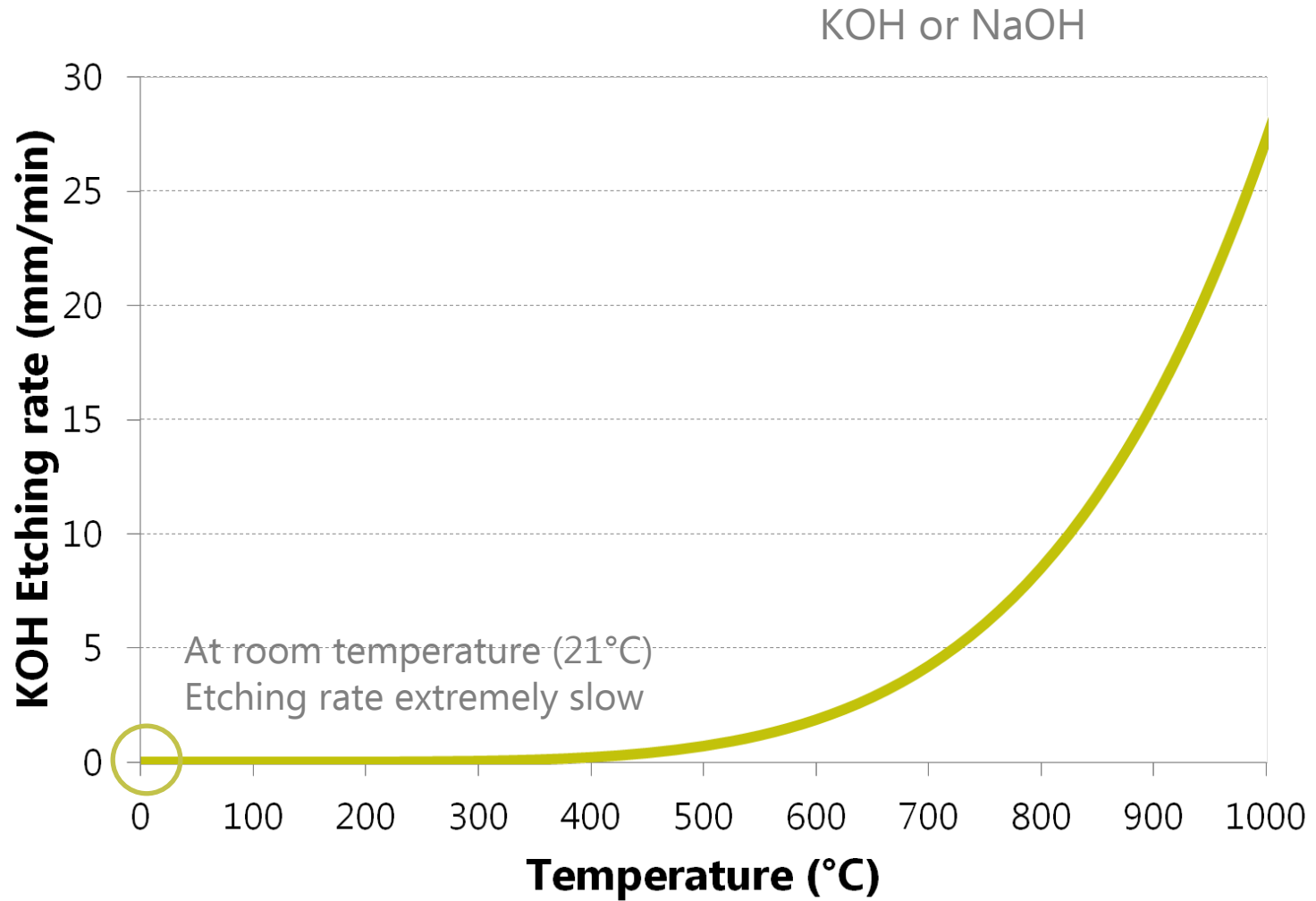
Gas film production around the tool



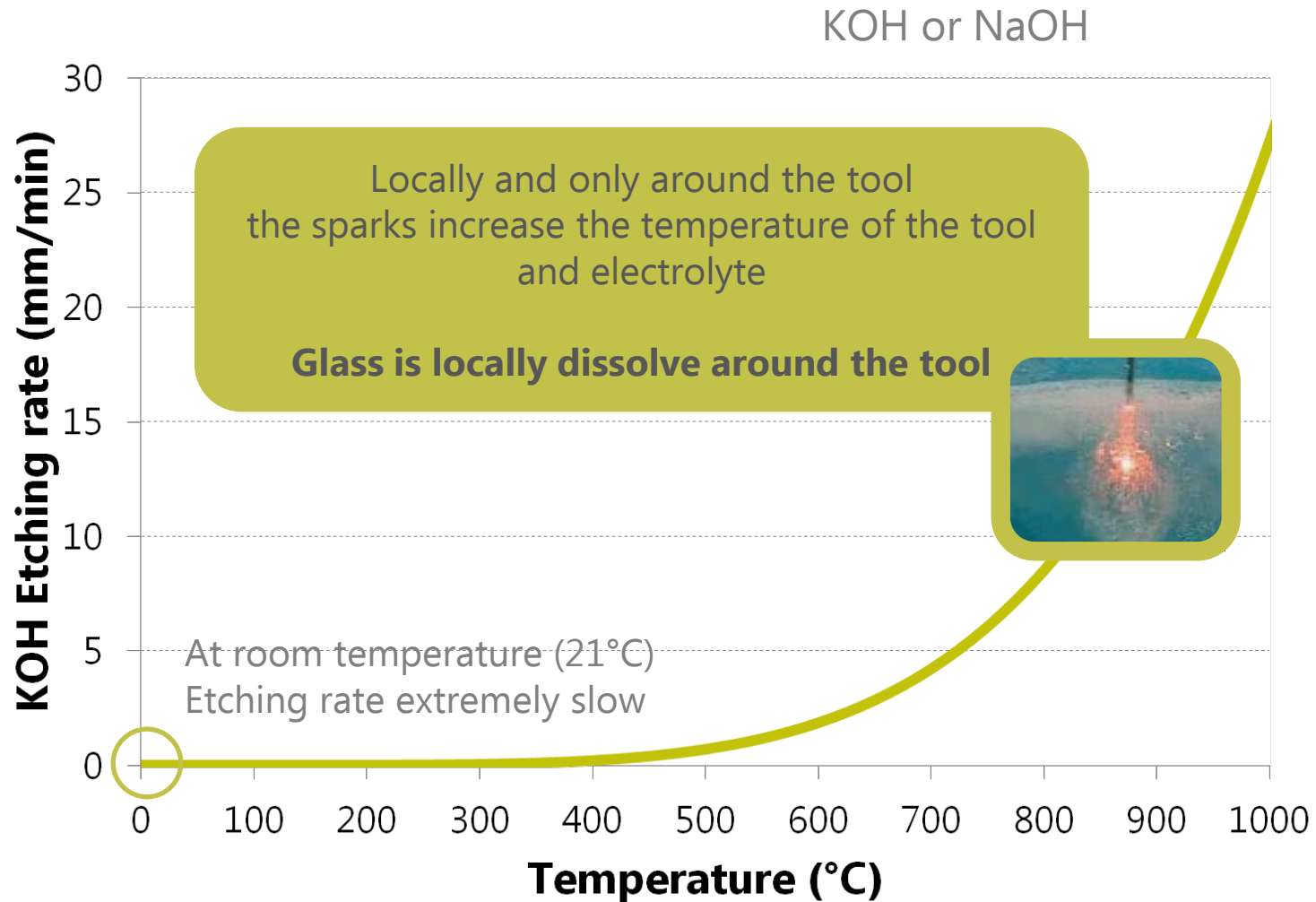
Gas film electrochemically formed
insulate tool from electrolyte ($t \sim 5\text{ms}$)



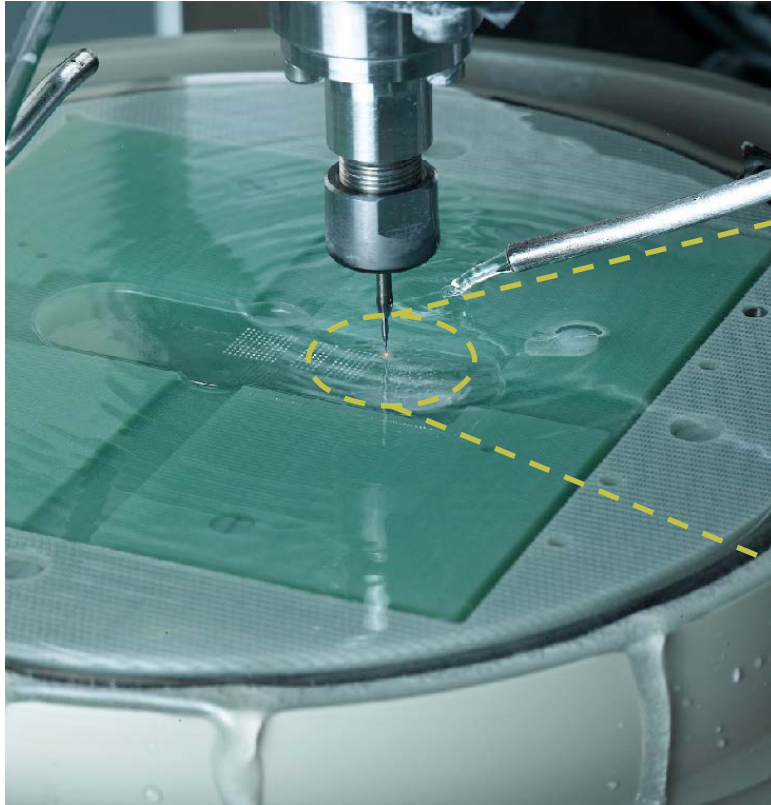
Sparks appear through gas film ($U > 30\text{V}$)



SACE Electrolyte

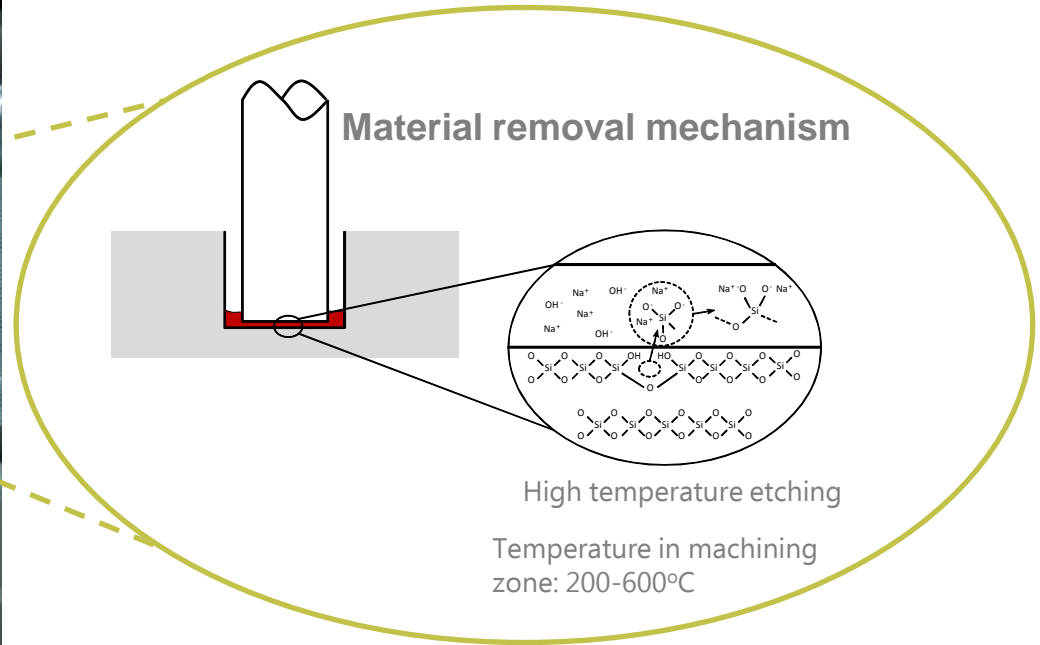


SACE a hybrid process

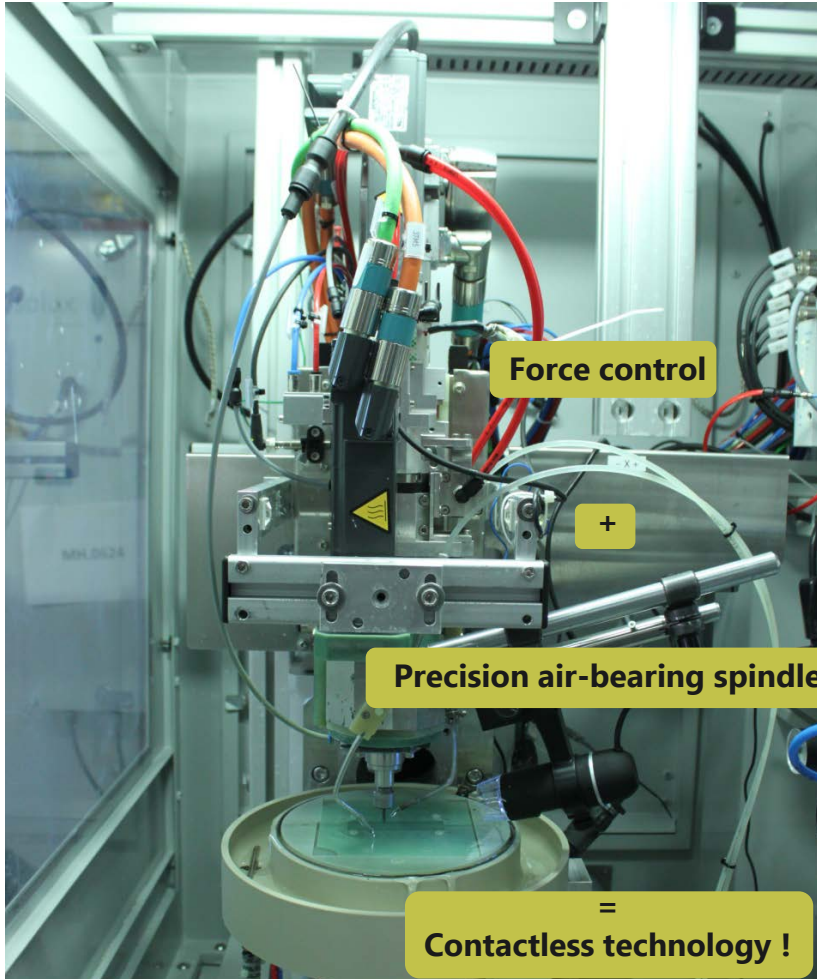


SACE combines advantages from 3 processes:

- Chemical → good surface quality
- Thermal → speed
- Mechanical → versatility



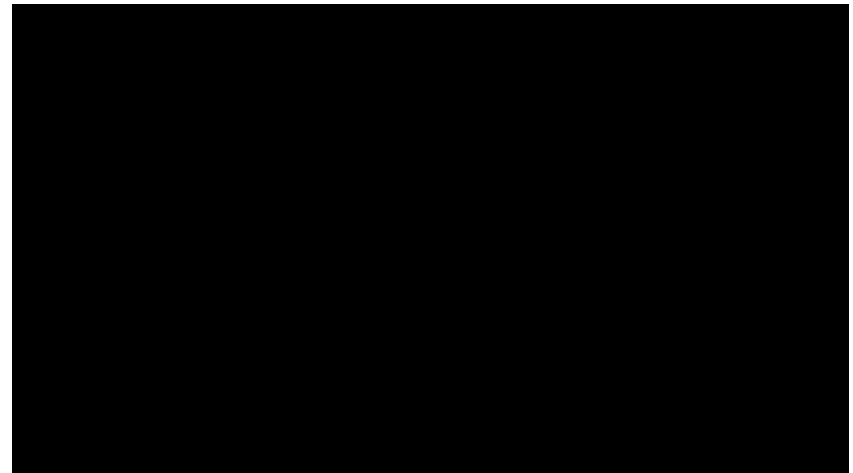
SACE a unique and patented technology



Glass is a strong and brittle material to machine



Our patented spindle machine the glass
with **zero force**



Polishing step

Only electrochemical process machines it !

Accuracy achieved and expected

- Test part done on demonstrator (with encoder for loop control)



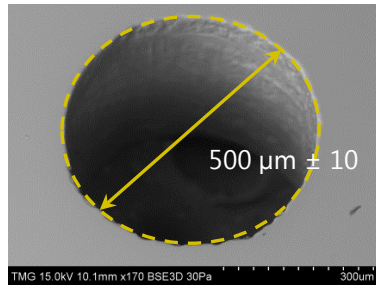
	Position		Diameter	Circularity
	X	Y		
NOM	0	0	0.22	0
MEAN	-0.0020	-0.0001	0.2260	0.0093
MAX	0.0007	0.0009	0.2278	0.0137
MIN	-0.0050	-0.0012	0.2234	0.0073
RANGE	0.0057	0.0021	0.0044	0.0064
STD DEV.	0.0016	0.0006	0.0011	0.0013

- Expectation on production machine (with linear scale for loop control)

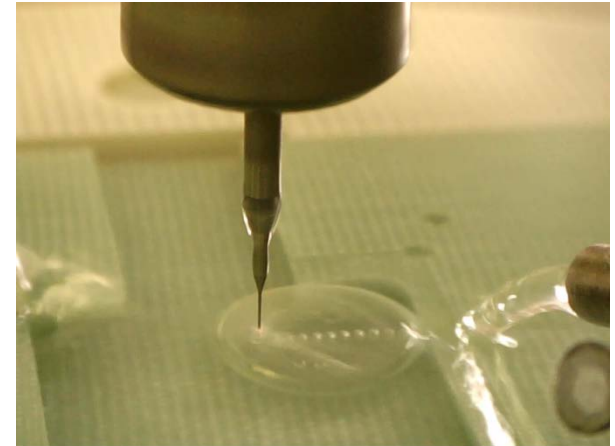
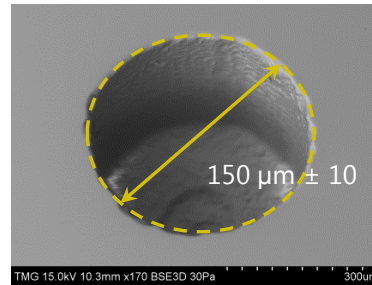
	Position	diameter	Circularity
STD DEV	<0.0005	<0.001	<0.001

Drilling

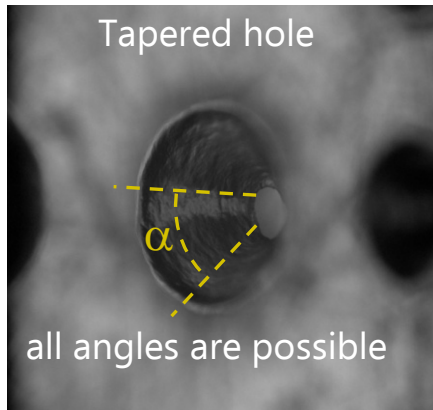
hole



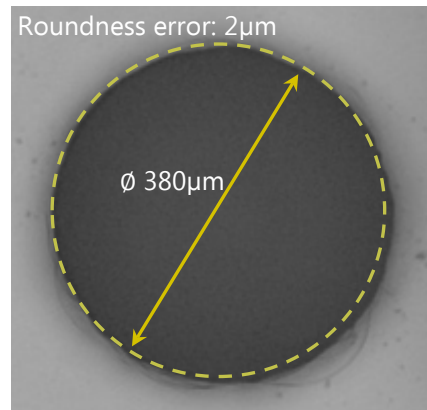
Blind hole



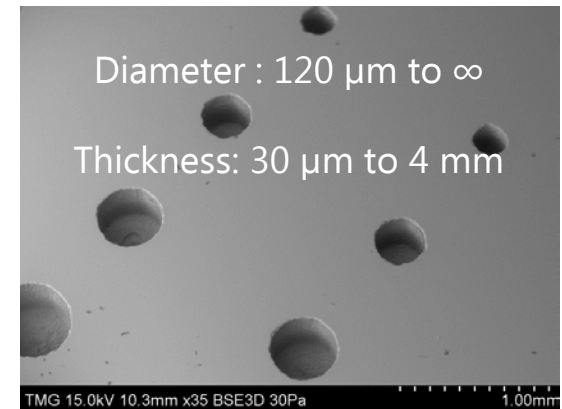
Tapered hole



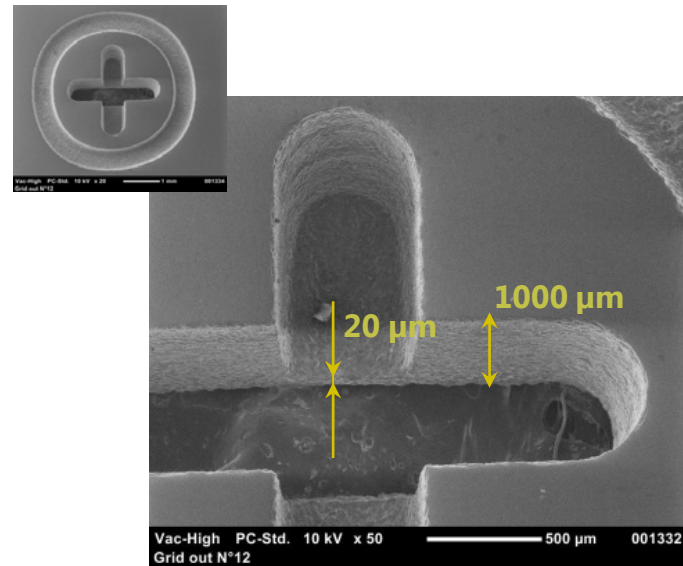
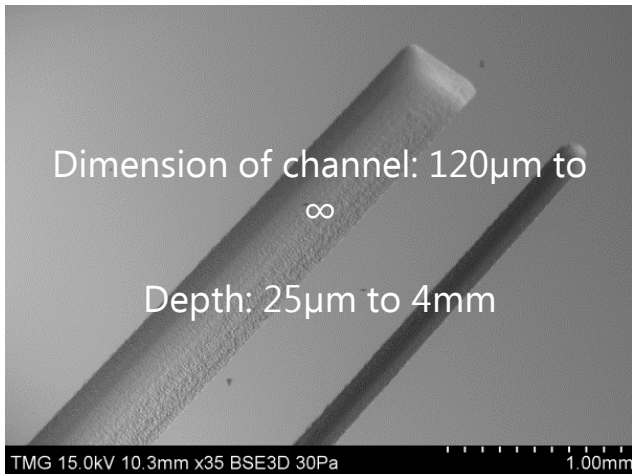
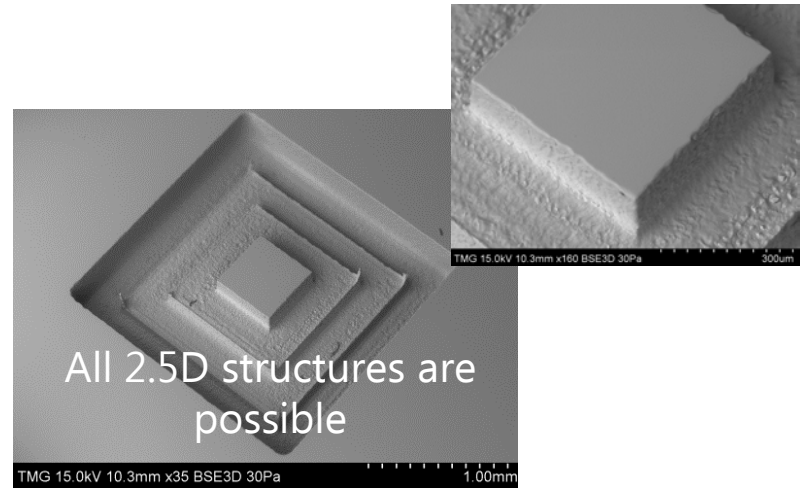
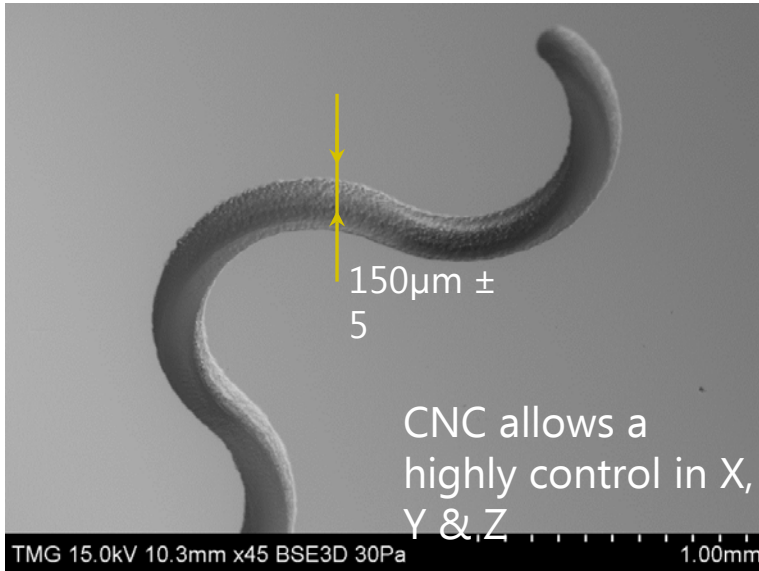
Roundness error: 2 μm



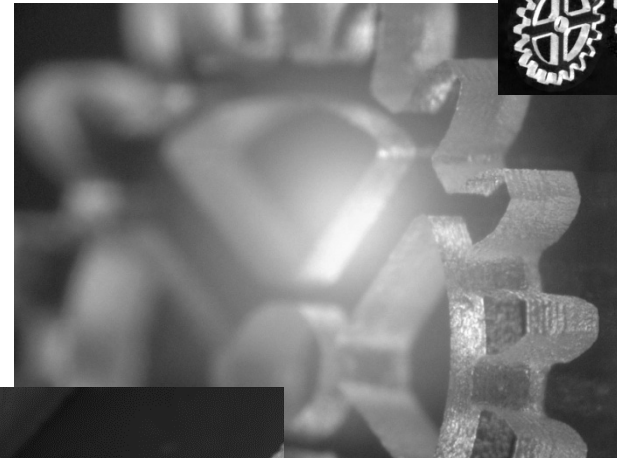
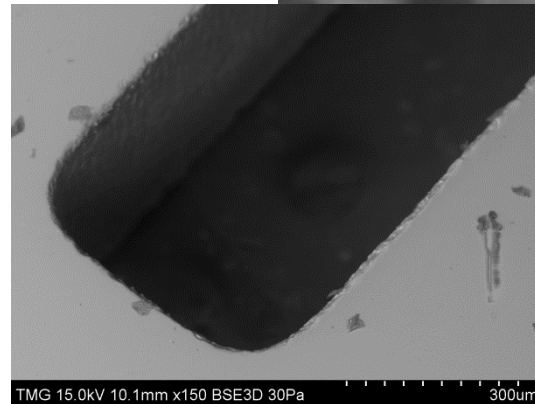
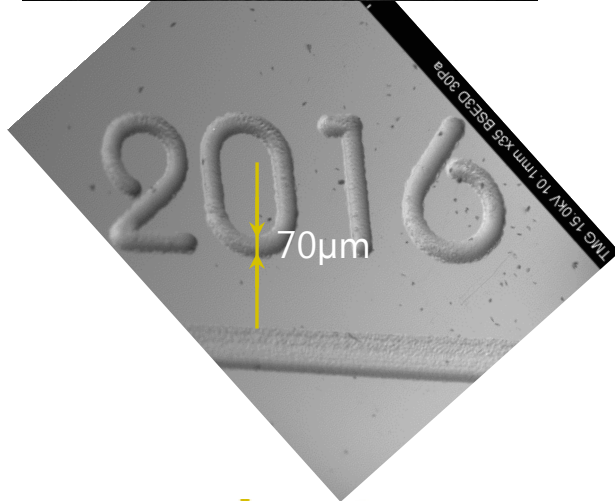
Diameter : 120 μm to ∞
Thickness: 30 μm to 4 mm



Milling

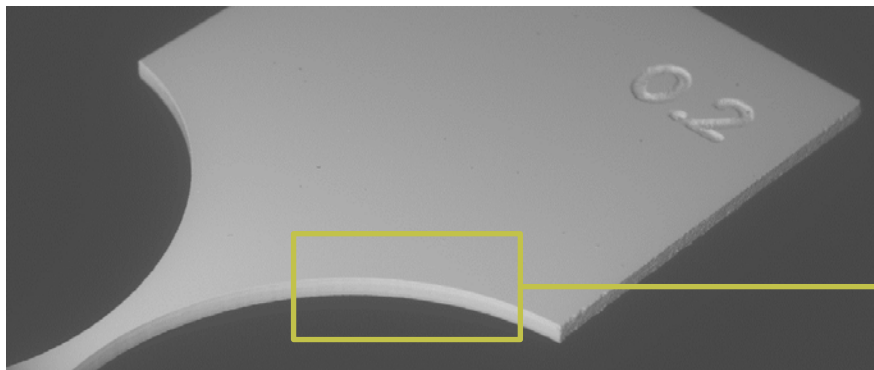
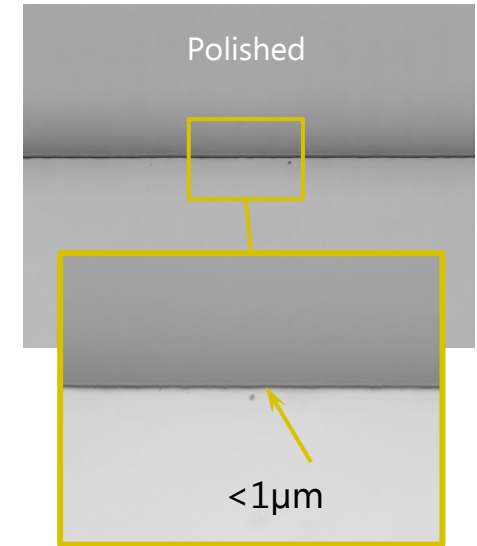
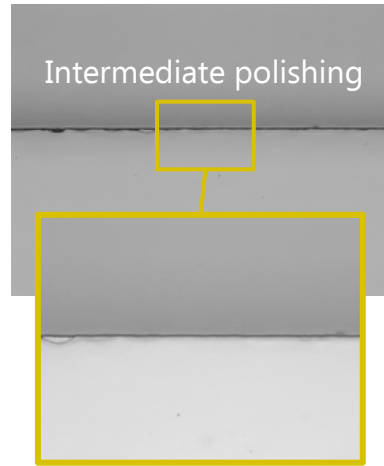
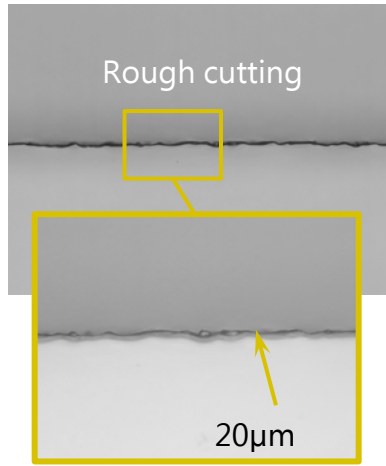


Engraving & cutting

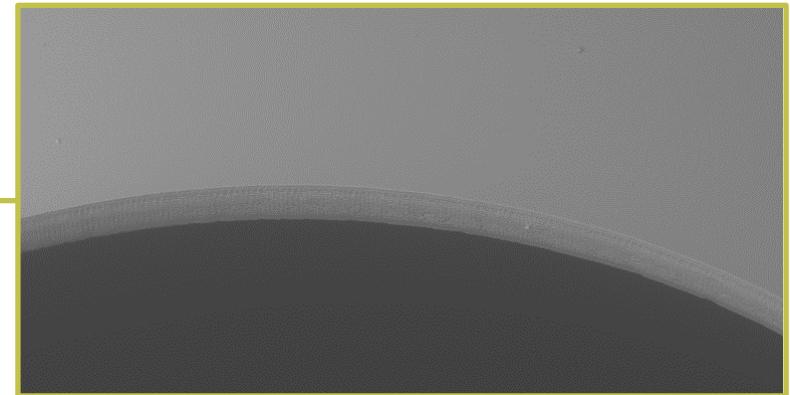


Cutting thickness:
30µm to 4mm

Surface finishing

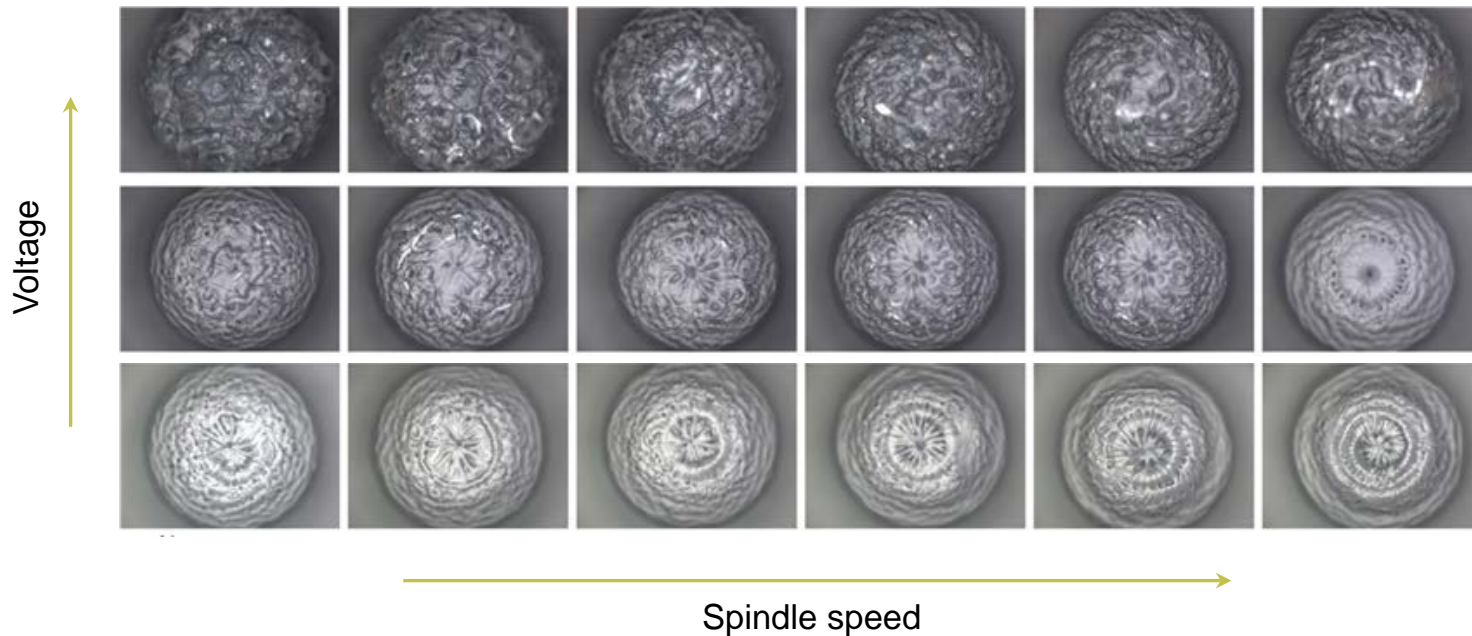


Glass thickness: 500 µm



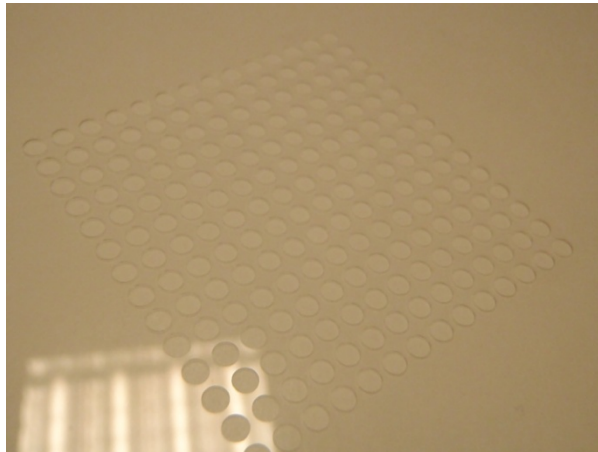
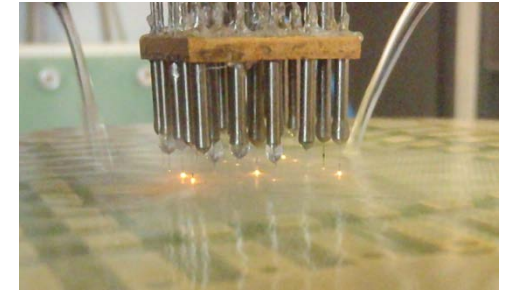
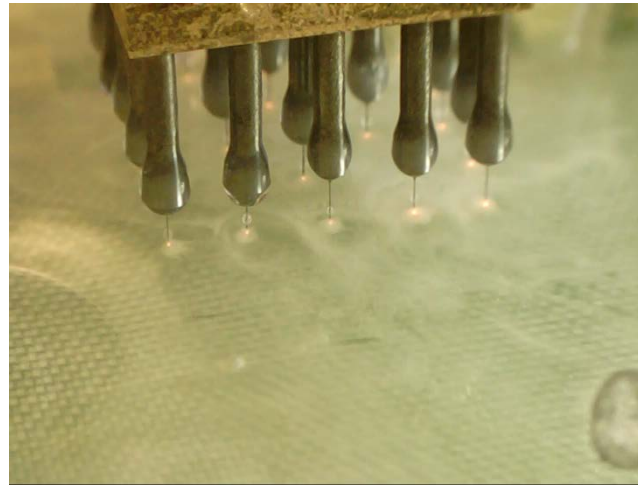
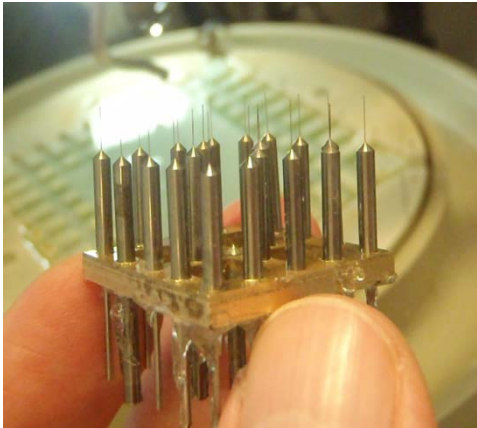
Surface texturing

Micro-hole texturation



Different machining settings generate different controlled surface patterns

High productivity with multiple tool approach



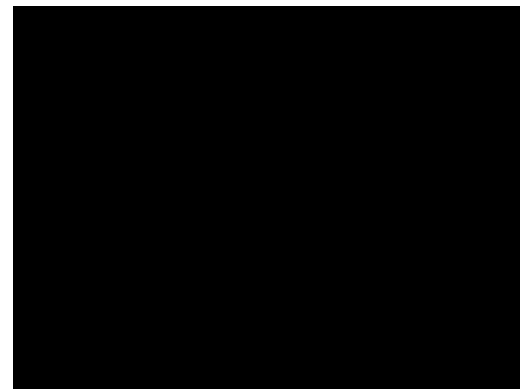
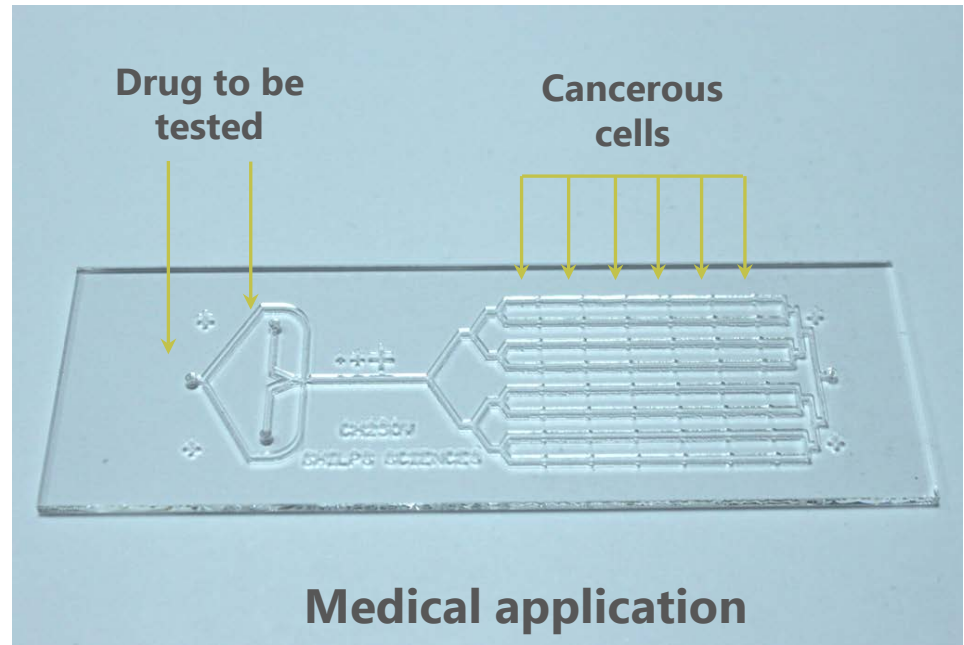
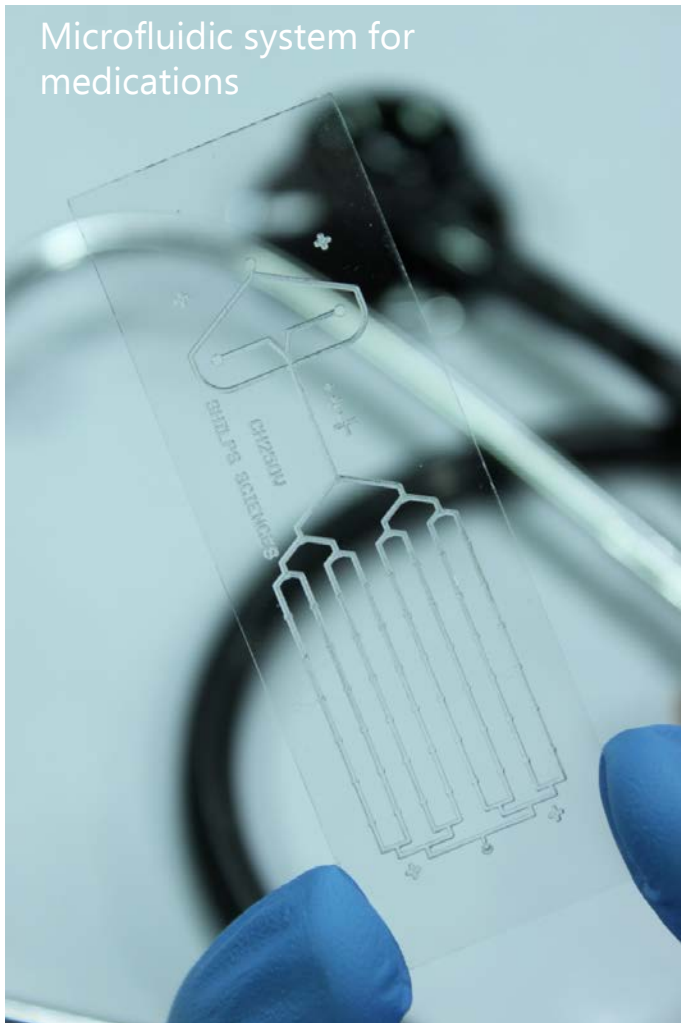
Example:

Diameter: _____ 2'600 μm

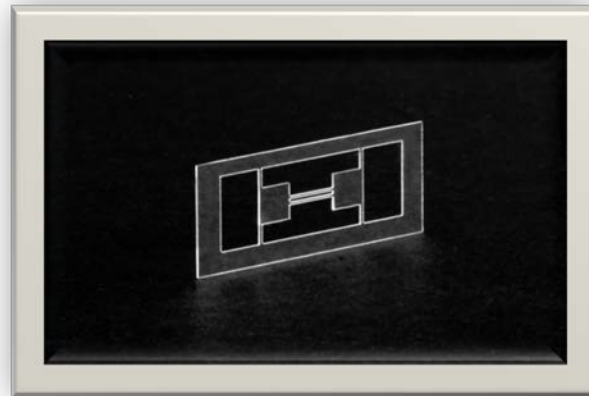
Thickness: _____ 300 μm

$$\frac{38 \text{ s}}{25 \text{ tools}} = 1.5 \text{ s/hole}$$

Lab on chip for high speed diagnostic



Samples



Modular machine concept



POSALUX - 4 Technologies

μ-Machining

EDM

SACE

Femto-LASER




PCB Micro Drilling and Routing

Milling machining

μ-Drilling & Routing

Milling

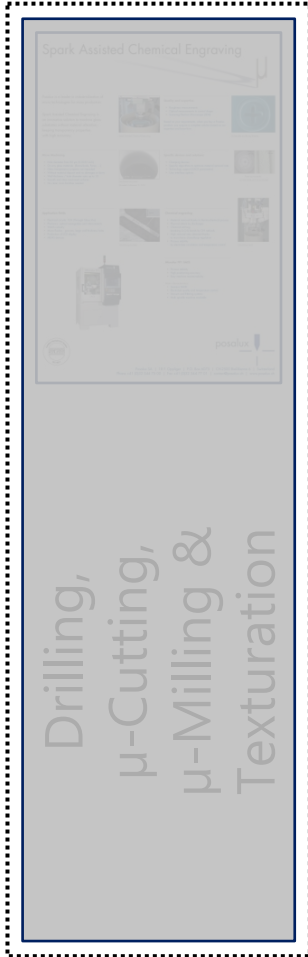
This block contains two vertical panels. The left panel is titled 'PCB Micro Drilling and Routing' and features a diagram of a drilling process and a photograph of a machine. The right panel is titled 'Milling machining' and features a diagram of a milling process and a photograph of a machine. Below the diagrams, the text 'μ-Drilling & Routing' is written vertically on the left and 'Milling' is written vertically on the right.



EDM micro-machining

μ-Drilling & μ-Milling

This block contains a vertical panel titled 'EDM micro-machining' with a diagram of the process and a photograph of a machine. Below the diagram, the text 'μ-Drilling & μ-Milling' is written vertically.



Spark Assisted Chemical Engraving

Drilling, μ-Cutting, μ-Milling & Texturation

This block contains a vertical panel titled 'Spark Assisted Chemical Engraving' with a diagram of the process and a photograph of a machine. Below the diagram, the text 'Drilling, μ-Cutting, μ-Milling & Texturation' is written vertically.



LASER Femto

Femto for μ-Drilling, μ-Cutting & Ablation

This block contains a vertical panel titled 'LASER Femto' with a diagram of a laser beam and a photograph of a machine. Below the diagram, the text 'Femto for μ-Drilling, μ-Cutting & Ablation' is written vertically.

After a long and successful history on EDM and μ -Machining technologies for robust industrial applications targeting:

- Micro machining of special and stressed parts
- Stable and repeatable Quality
- Accuracy for mass productions
- Mass-production with flexible and versatile possibilities

Posalux focus on **Femto Laser Technology** for high precision **μ -Machining** since 2011

First serial Femto Laser machines are in production since end of 2014 and work 24/7

Posalux made the choice to:

- ↪ **develop niches applications** which require a high level of skills
- ↪ build **long term industrial partnership** with our customers

Posalux **is not an integrator** of Laser equipments, we **develop industrial processes** to meet **Customer Quality requirements**.

For this, measurement equipment as **Gauges, SEM, Flow-bench** are available @ Posalux to document the manufacturing processes

Posalux build and continues to build **partnership with key actors in Industrial Femto Laser applications**

- ↪ 2 suppliers/partners for Femto Laser sources (*less than 300 fs*)
- ↪ 2 suppliers/partners for Precession heads

Laser Sources

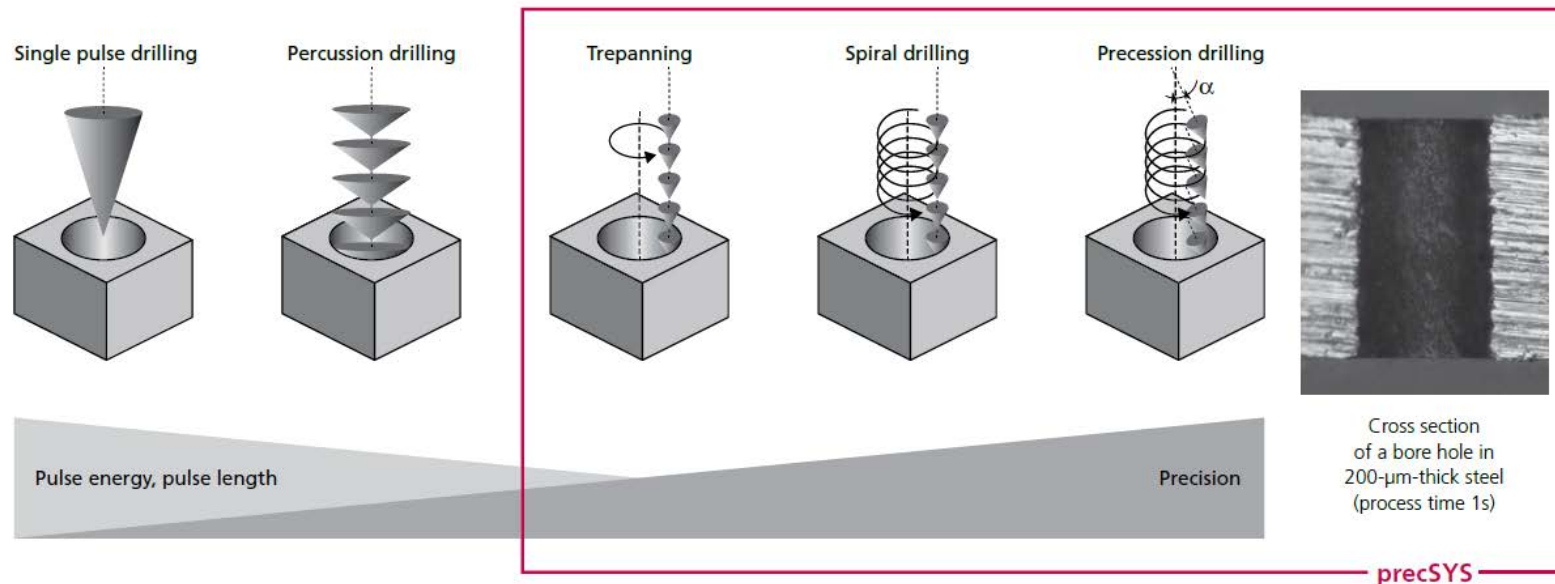
- LIGHT CONVERSION (LT based + WW) _____ *More than 3 years*
- AMPLITUDE Systèmes (FR-US based + WW) _____ *More than 2 years*

5 axis Precession Head

- SCANLAB (GE based + WW based) _____ *More than 3 years*
- CANON (WW based) _____ *More than 1 year*

Flexible 5-axis micro processing

- The possibility to position the laser beam in 5 axis (x, y, z, α, β) offers highest flexibility for process development
- Typical applications: Drilling, Ablation, Structuring, Cutting



PERFORMANCE

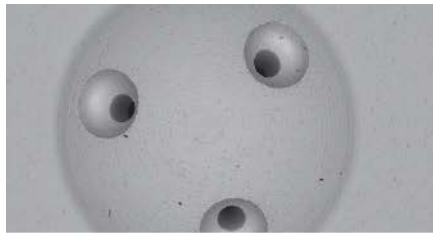
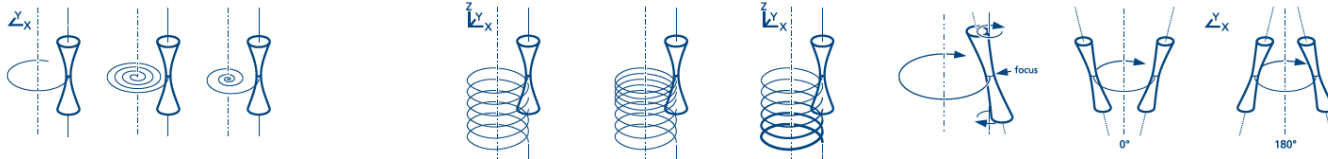
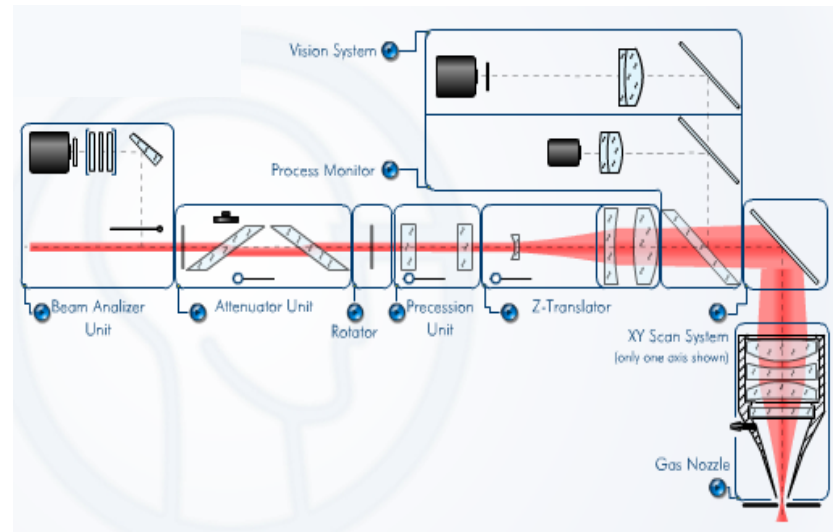
DRILL PARAMETER	TYPICAL VALUE
Hole Diameter Range ¹	50 μm -500 μm
Material Thickness ^{1,2}	~ 1 mm
Cycle Time ³	~ 2 seconds/hole
Taper Angle Range ¹ (full angle)	Pos. & neg. to 10°
Hole Circularity	> 95 %
Surface Quality (inside wall)	$R_a < 0.1 \mu\text{m}$
Diameter Resolution	< 1 μm
Diameter Repeatability	< 0.4 %
Hole Position Accuracy ⁴	$\pm 1 \mu\text{m}$

¹ Please inquire regarding features outside this range.

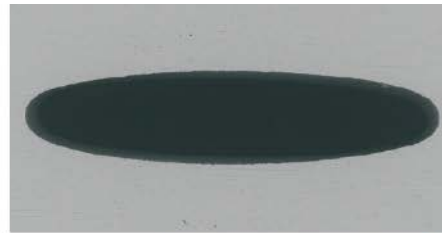
² Maximum material thickness is dependent on hole dimension.

³ Cycle time quoted for 200 μm diameter hole in 200 μm thick 440 stainless steel.

⁴ Hole position repeatability is dependent on overall workstation design and quality.



2 mm

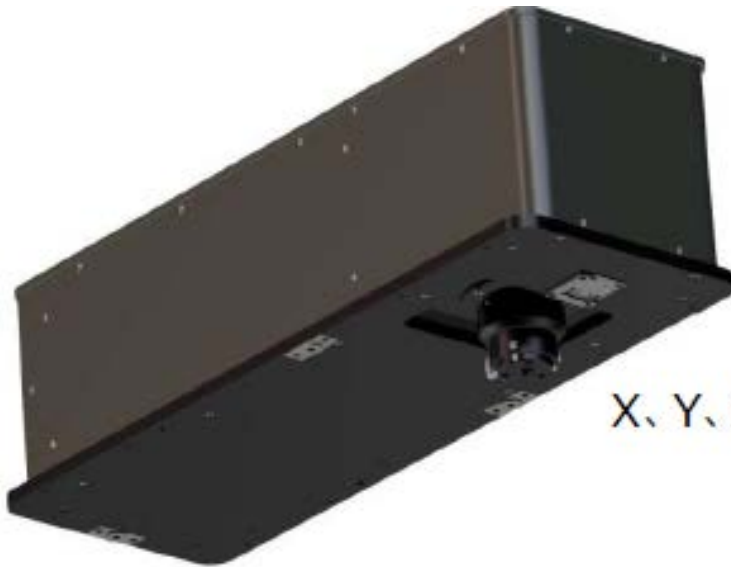


200 μm



300 μm

- Partnership **since 1 year**
- Joint-development **of Customer Applications**
- **Started important customer project** beg. of 2016 for Green Wavelength Applications
- **4 serial machines in production** by end of 2016 with nIR Canon heads

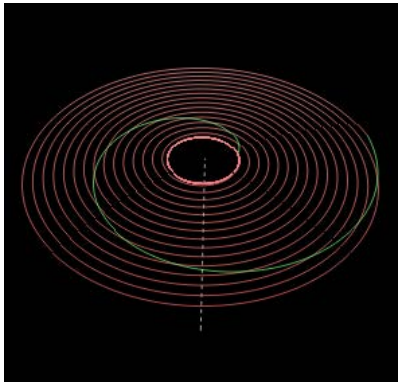


CANON precession head MA-501 is manufactured with original CANON components (electronic, optics, encoder, scanner, ...)

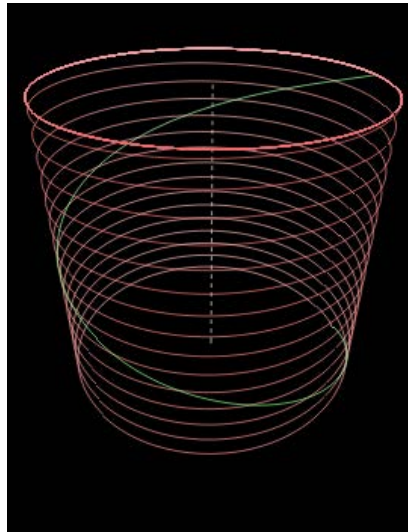
X, Y, Z, θ_x , θ_y scan

There are various ways to drill a hole, but all strategies are always based on a combination of basic movements

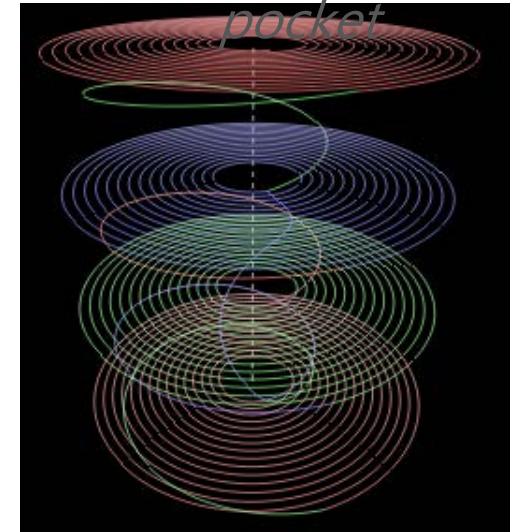
spiraling

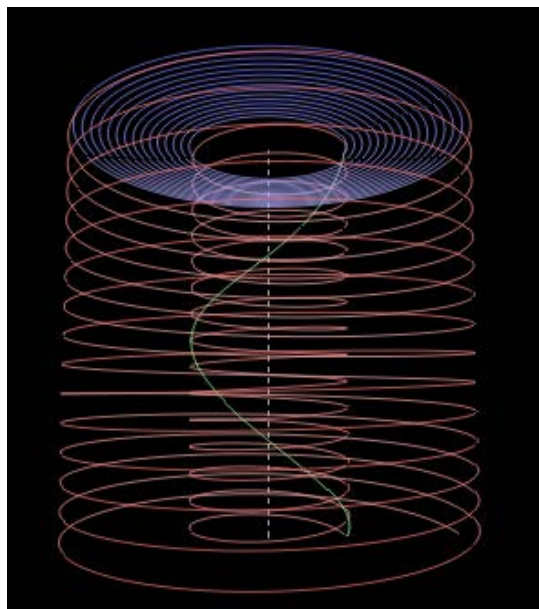


helical



spiraling by pocket



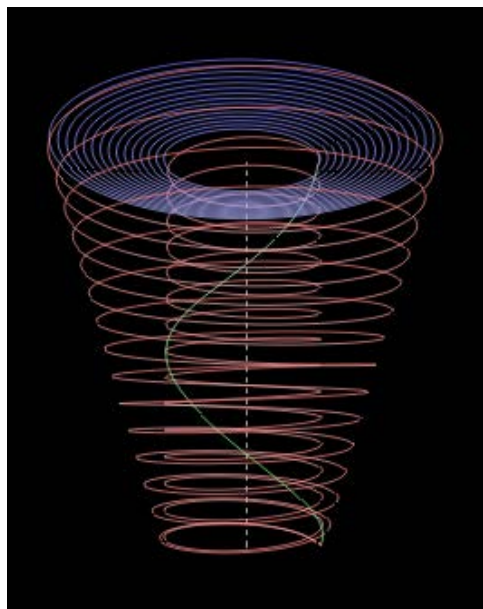


Peckhole :

↪ helical

Precession hole :

↪ helical spiraling

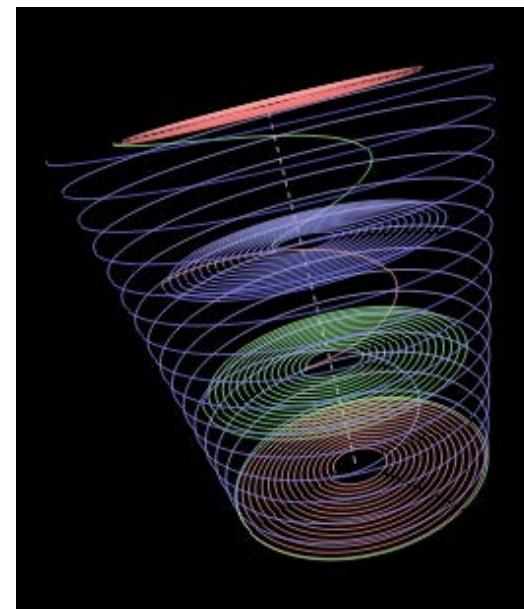


Peckhole :

↪ helical

Precession hole :

↪ conical helical spiraling



Peckhole :

↪ spiraling pocket

Precession hole :

↪ Conical helical spiraling

LASER FEMTO Applications



Dedicated team of 5 Engineers for process development and support of customer ramp-up phase

Available equipments for these activities:

- ⇒ 2 demonstrator machines
- ⇒ 1 "mono" **serial machine**
- ⇒ 1 bench on active table
- ⇒ 4 precessions heads, 4 Femto Laser sources

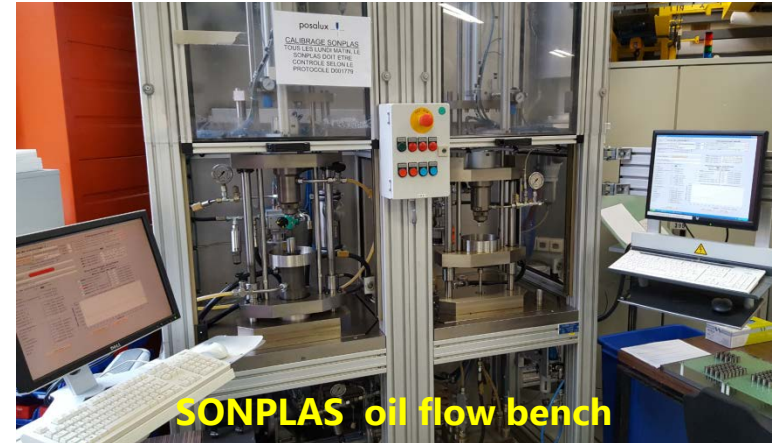
Werth Fiber probe measurement equipment, **SEM**, accurate **microscopes**, Hydraulic **flow bench** (to 200 bars, R&R = 10%), **Confocal Laser 3D** surface finish measurement (Oct. 2016)



**WERTH – VIDEO CHECK
IP400**



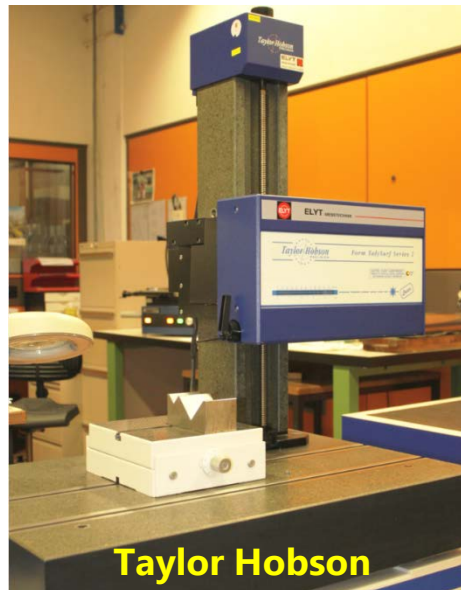
LEITZ – PMM 12106



SONPLAS oil flow bench



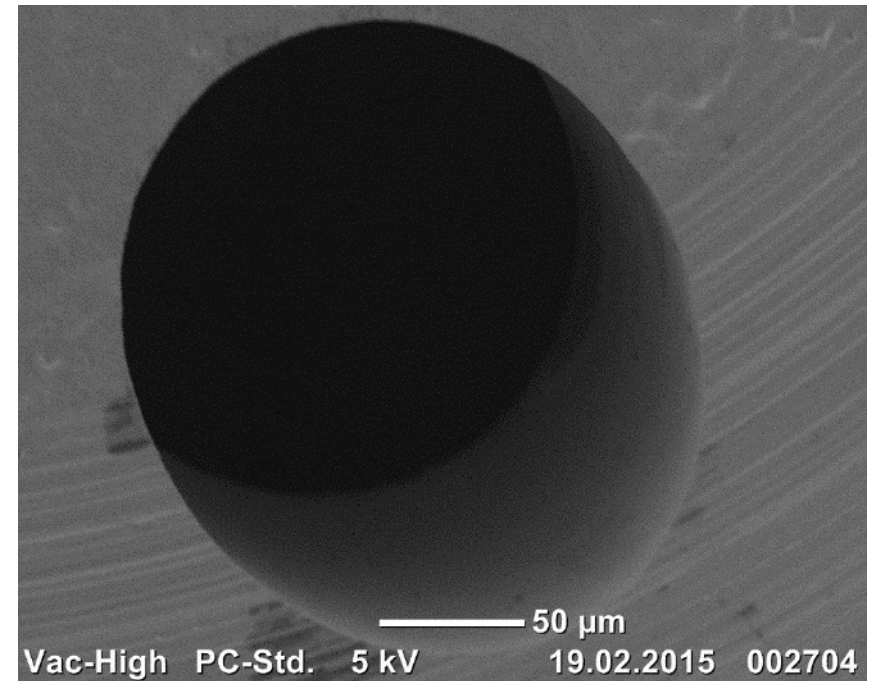
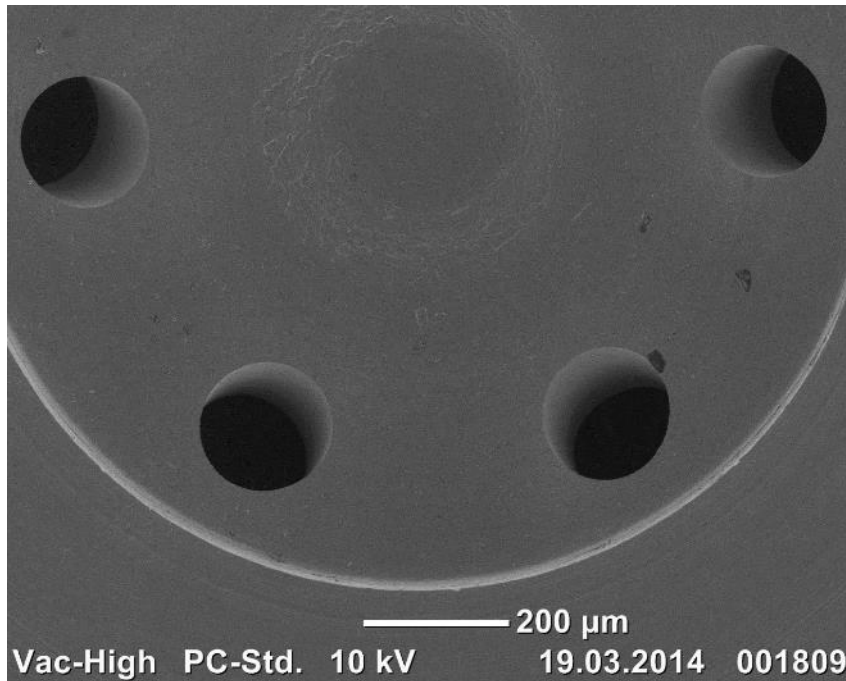
**IMPEX MICROVISION
PRO X3**

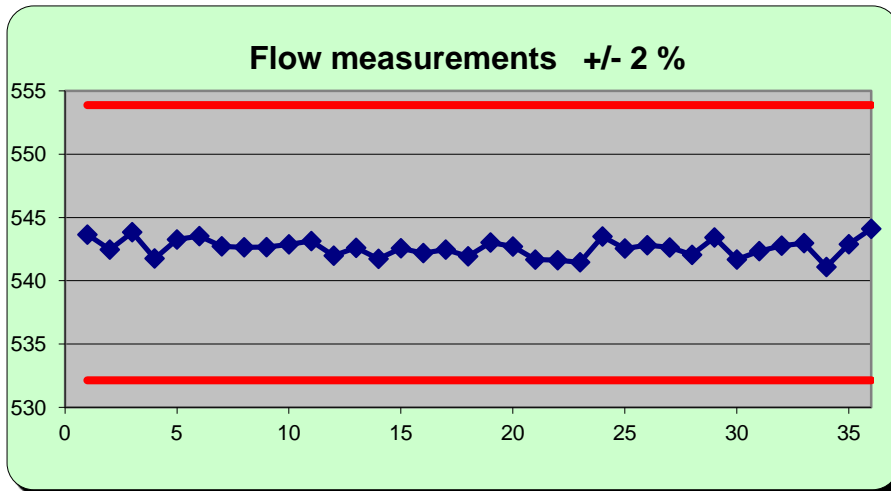


Taylor Hobson



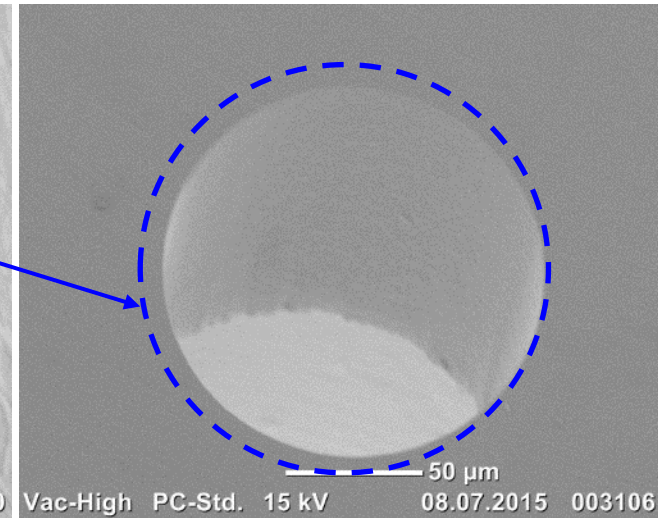
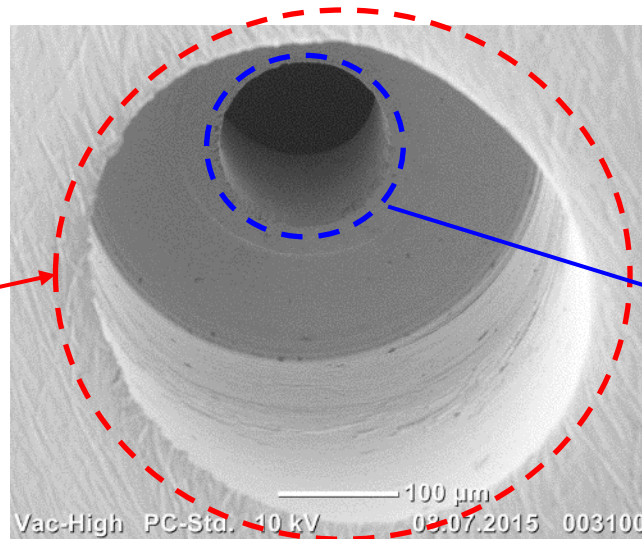
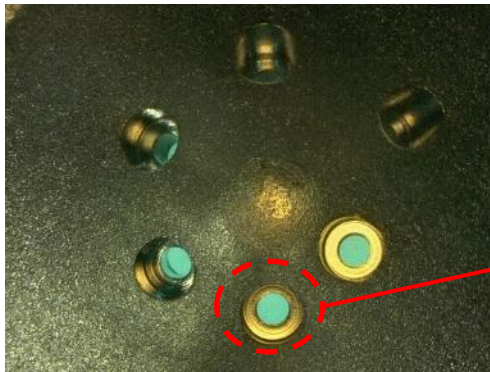
KEYENCE – Confocal Laser 3D





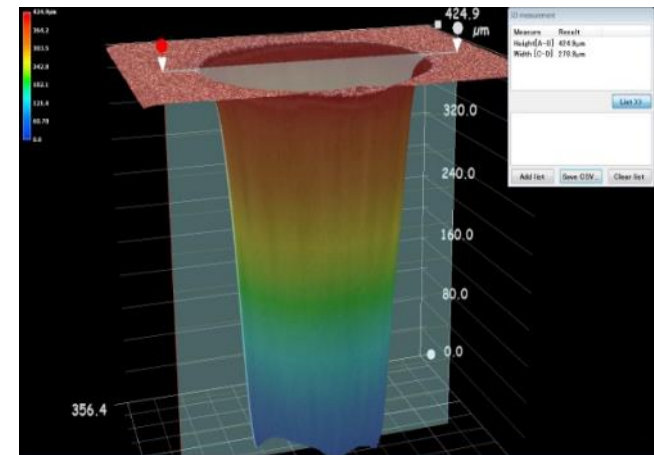
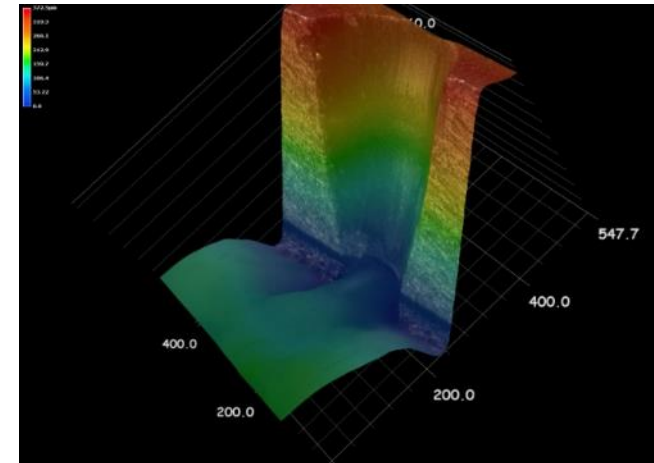
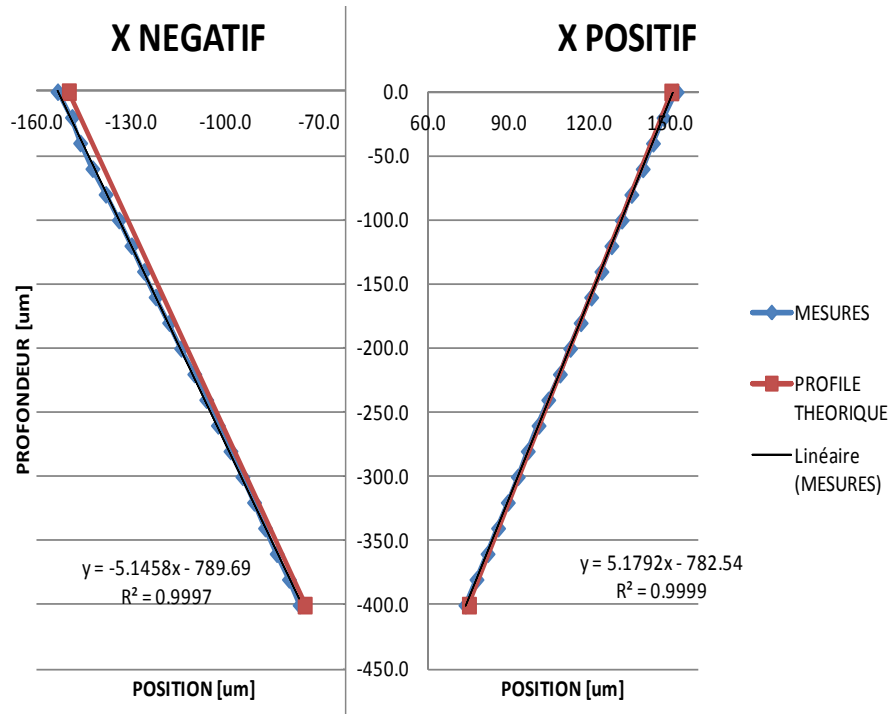
Orifice diameter = 140 μm

Cp	5.10
Cpk	4.91



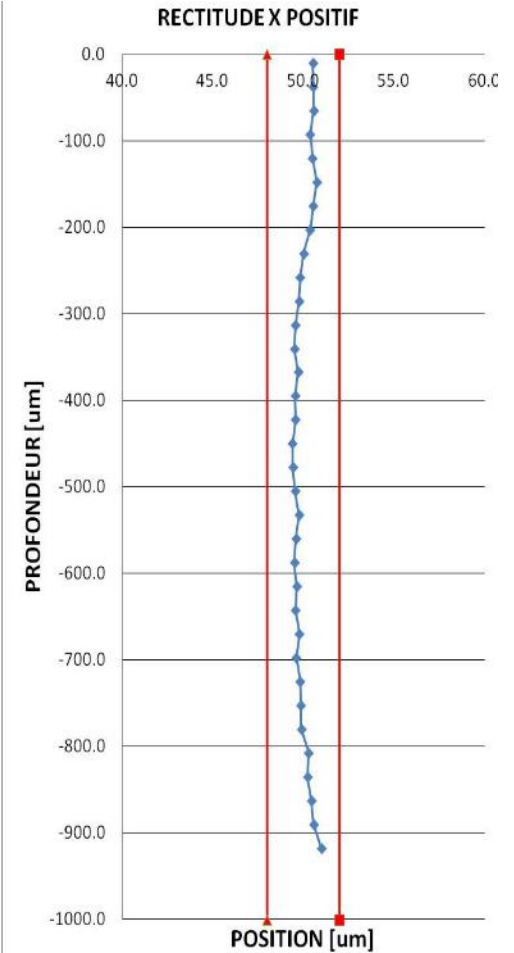
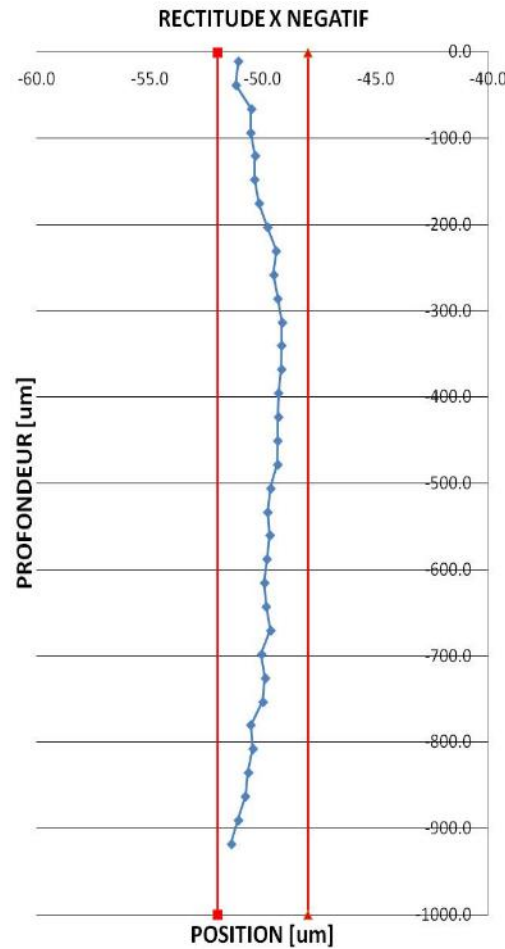
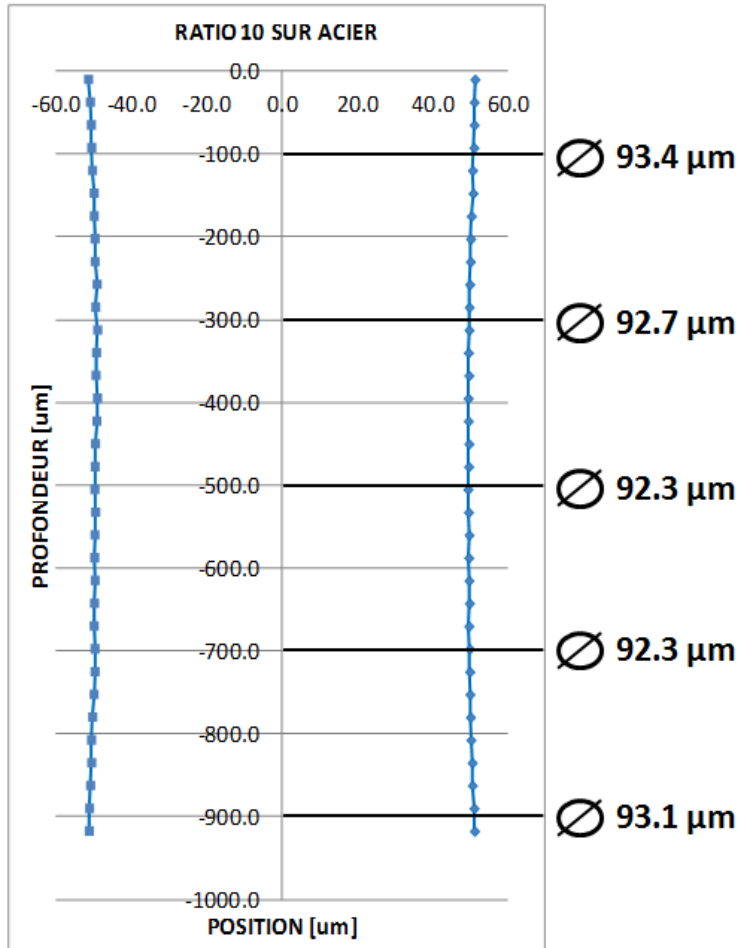
Tapered hole drilling

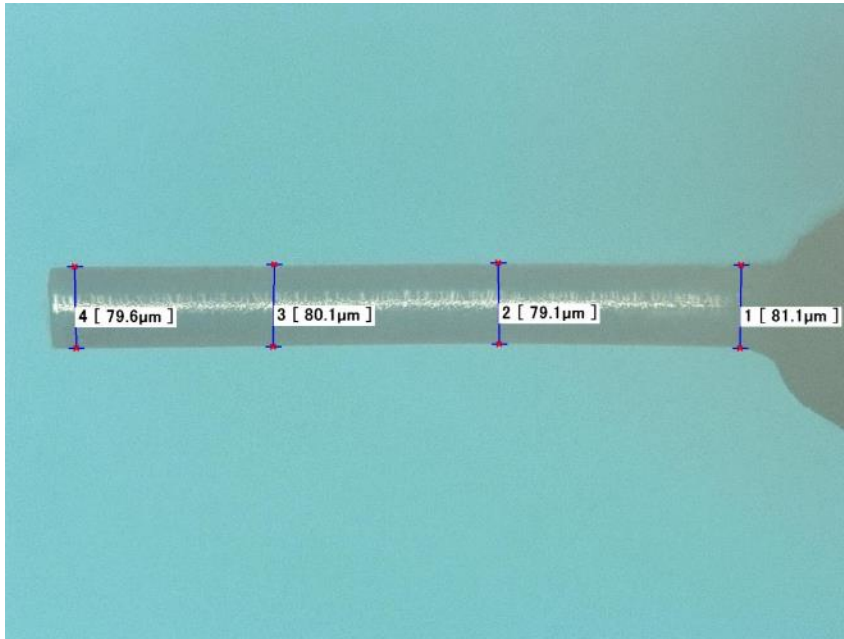
-15° to +23° in Steel



Hole drilling

Steel Ratio 1:10

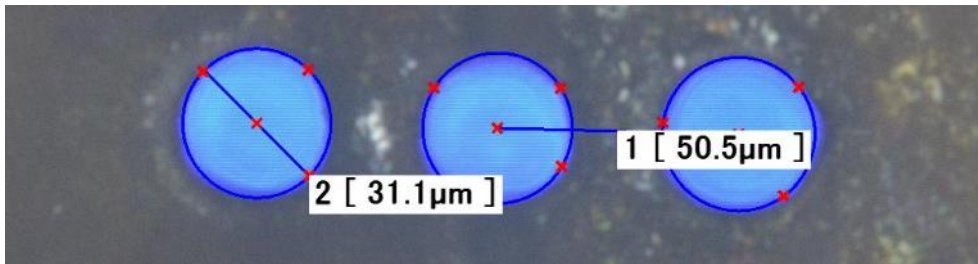
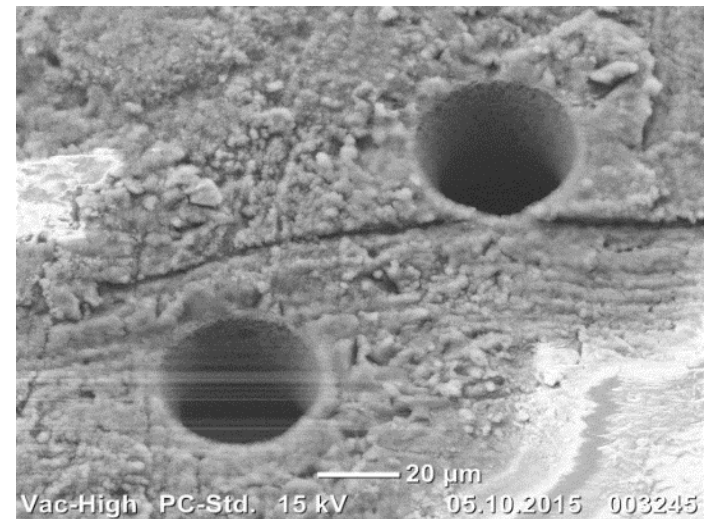




Steel : Ratio 1:10

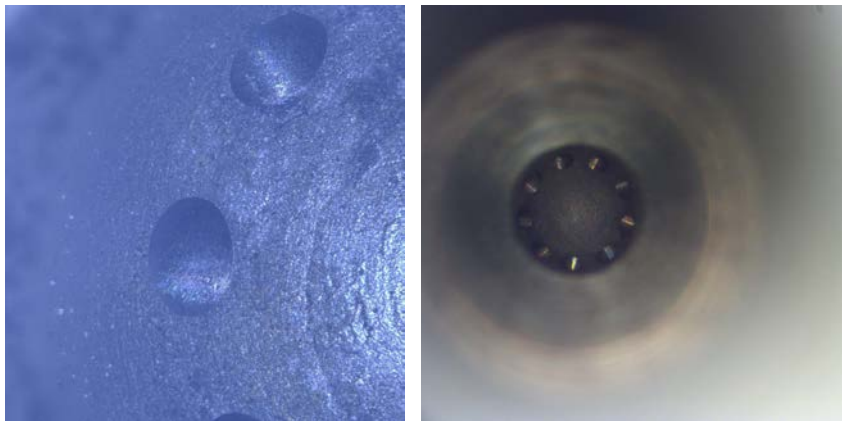
∅ 80 μm, depth = 800 μm

Peek : Ratio 1:15

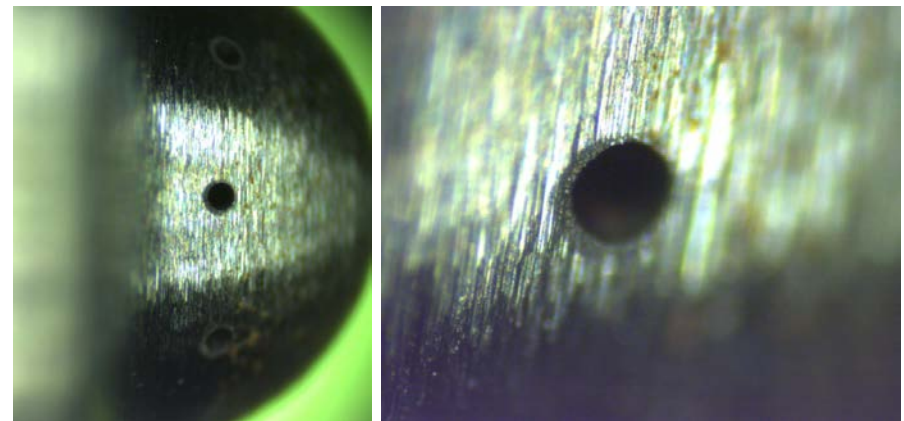


- 9 spray holes
- K factor 2 +/-0.5
- Thickness : about 1.1 mm
- Raw material : 34033 h-13
- No damage, no "injury" coming from the beam, inside the micro sac.
- Flow stability @ +/-2%, $C_p > 1.6$
- **Life of the backwall protection > 1000 holes**

Diameter surface OD: 0.203 mm

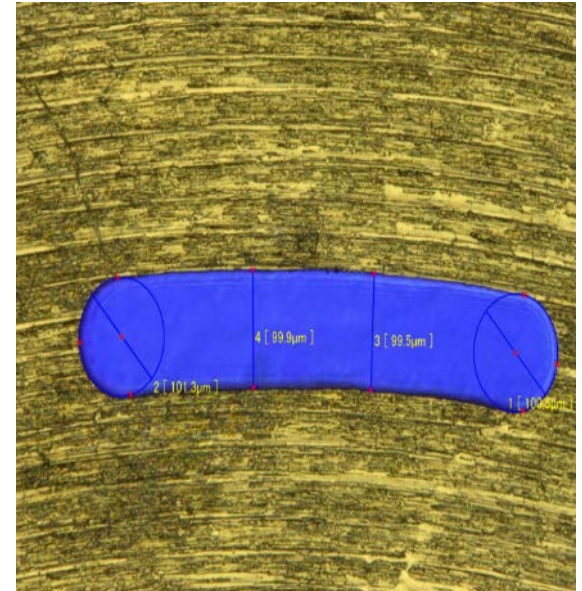
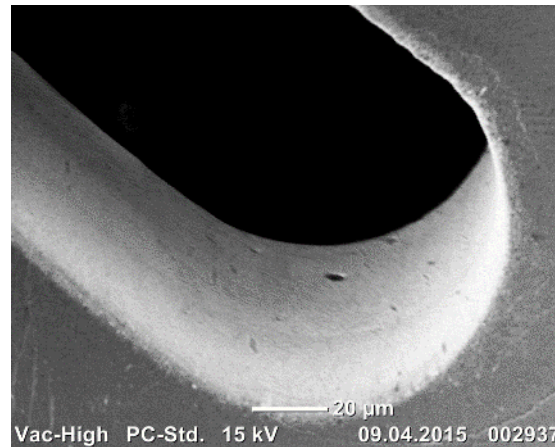
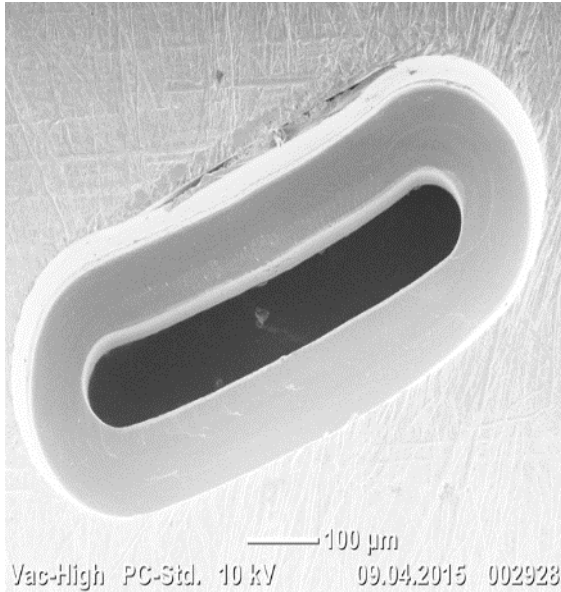


Diameter surface ID: 0.181 mm



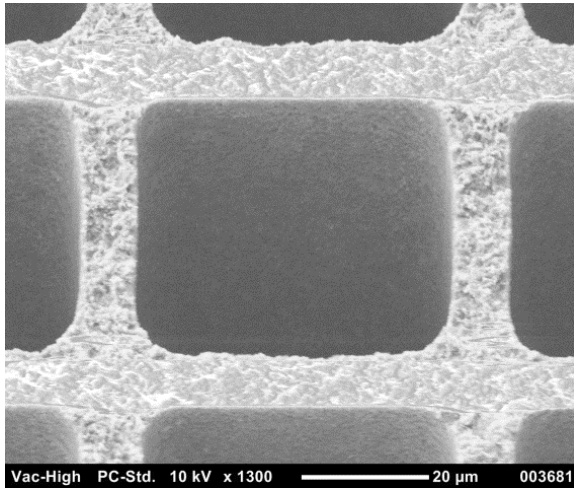
Machining and cutting "oblong shape"

Steel



Machining of square holes :

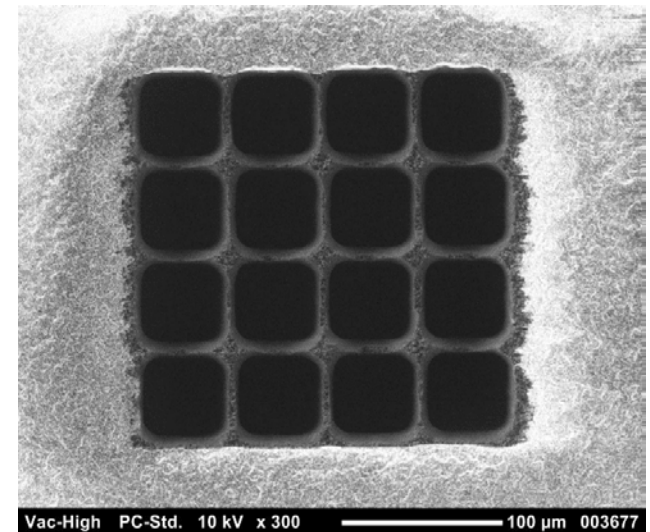
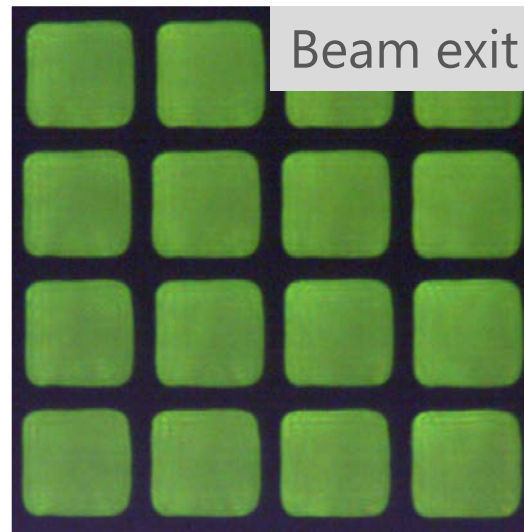
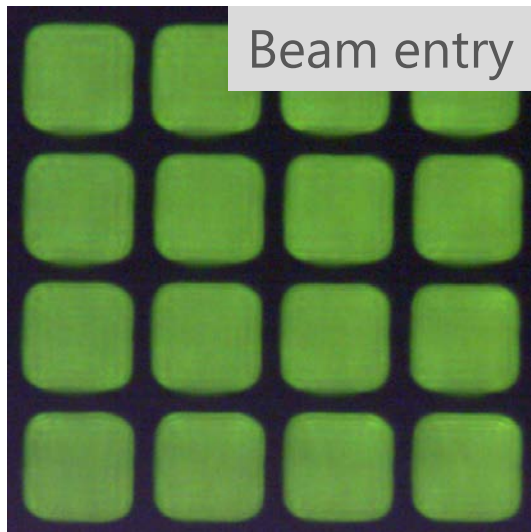
Ceramic Al_2O_3



Square holes 50 μm x 50 μm x 500 μm , pitch 60 μm

Radius ≈ 13 μm (radius of the beam at focal point)

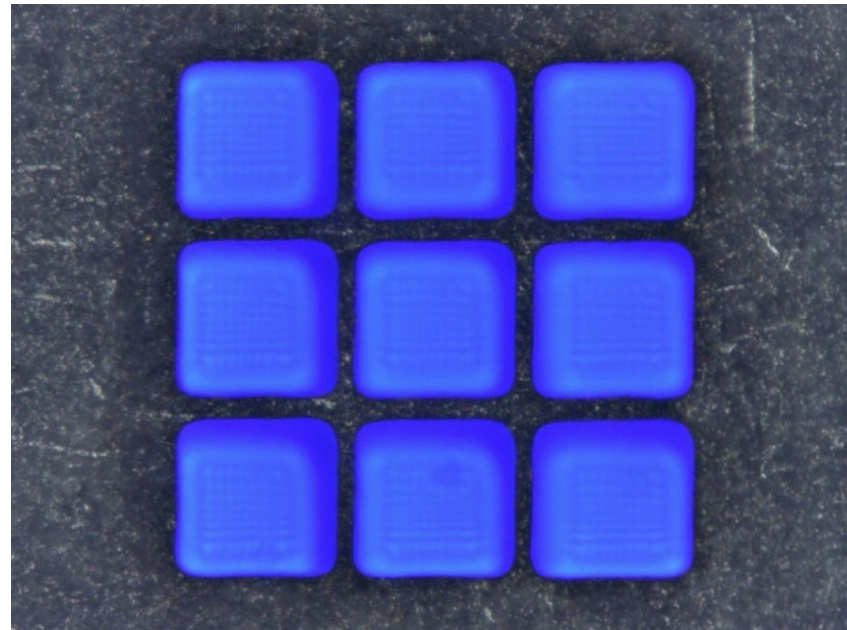
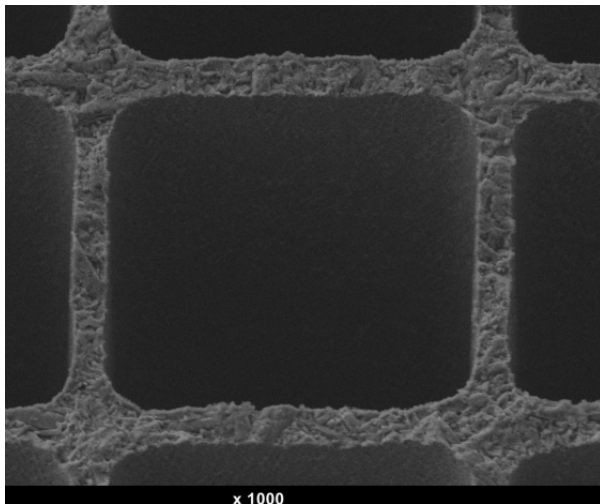
Process cycle time per hole: 15 s
(not optimized)



Machining of square holes :

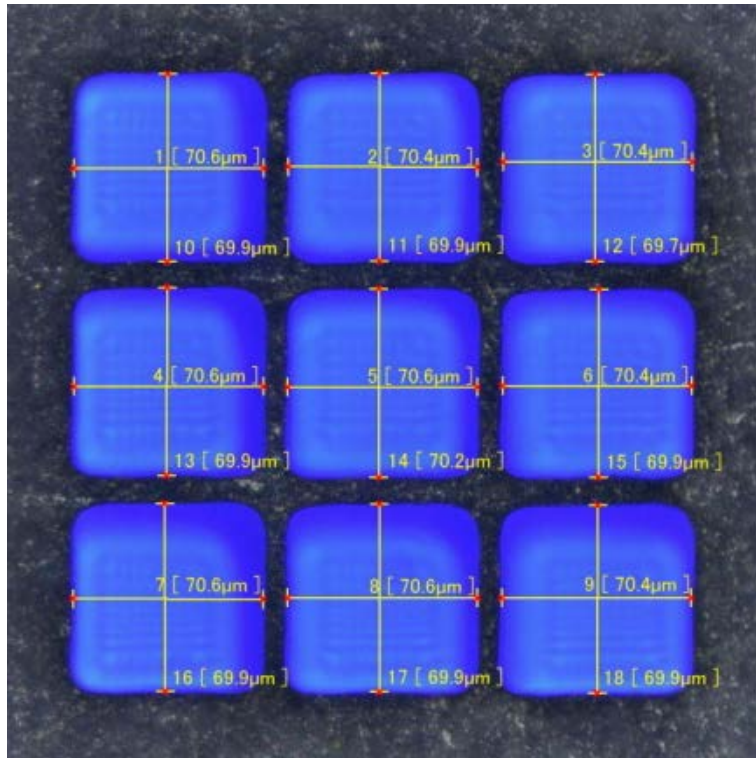
Si_3N_4

- Thickness material : 0.32 mm
- Cycle time process per square hole < **2.4 sec** (not optimized)



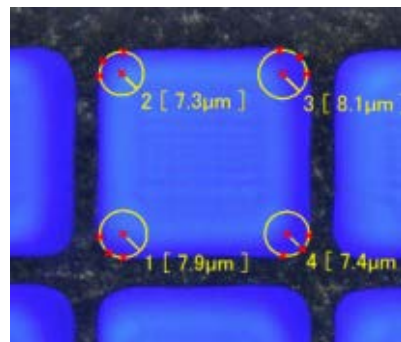
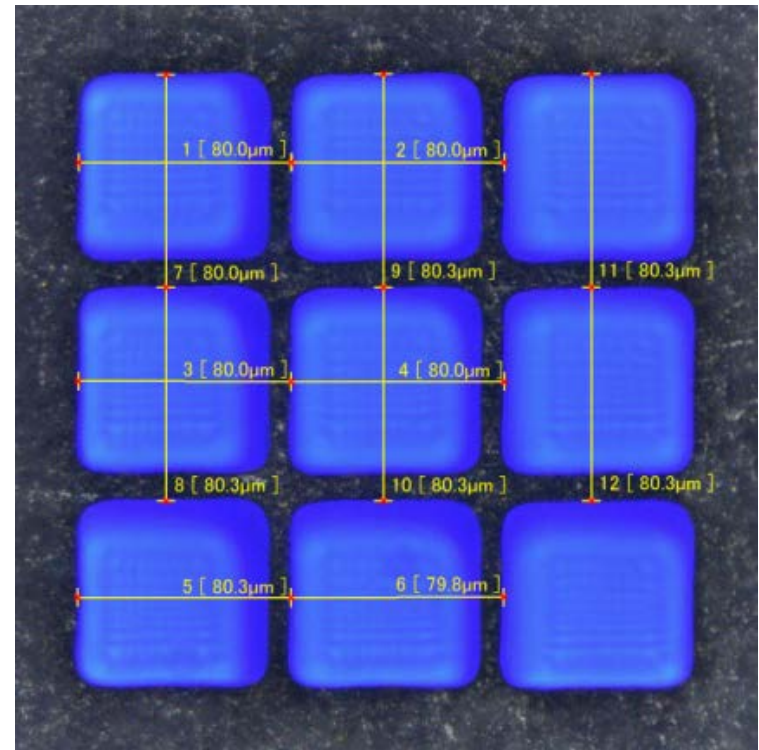
Machining of square holes :

Si_3N_4



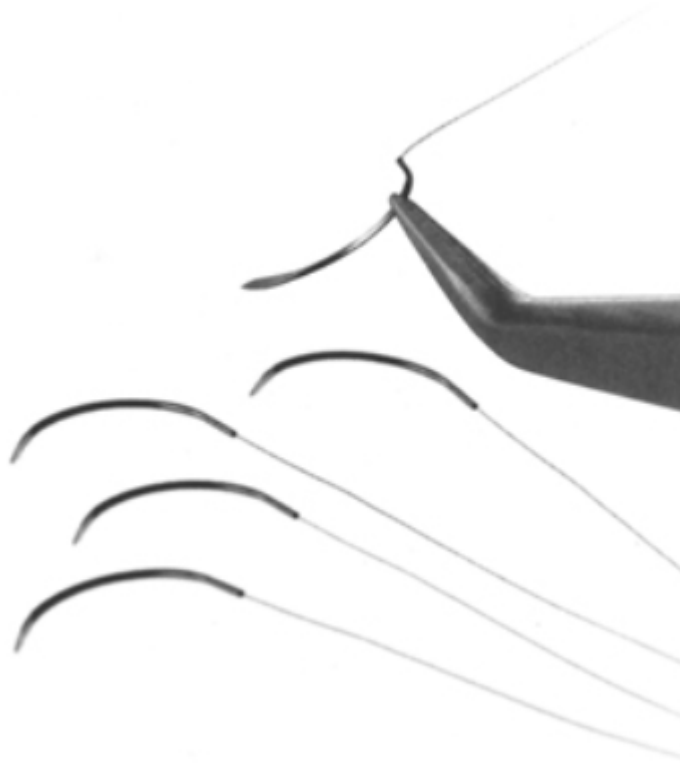
Square holes $70 \mu\text{m} \times 70 \mu\text{m} \times 320 \mu\text{m}$,
pitch $80 \mu\text{m}$

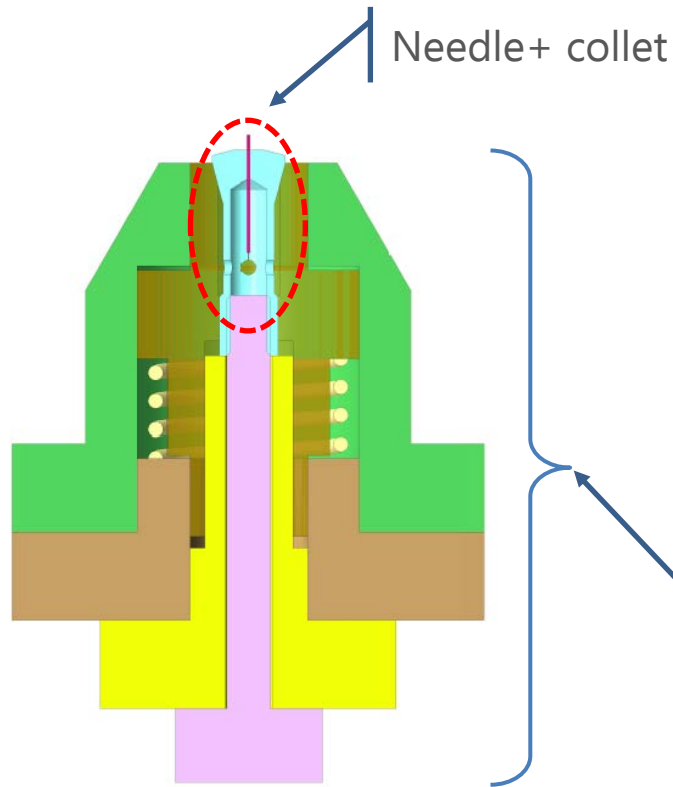
Radius $\approx 7 \mu\text{m}$ (radius of the beam at focal point)



Surgical Sutures Needle drilling with Femto Laser

Drilling of a blind hole with a taper at entry . Diameter / Length Ratio 1:9
Hole diameter down to 60 μ m





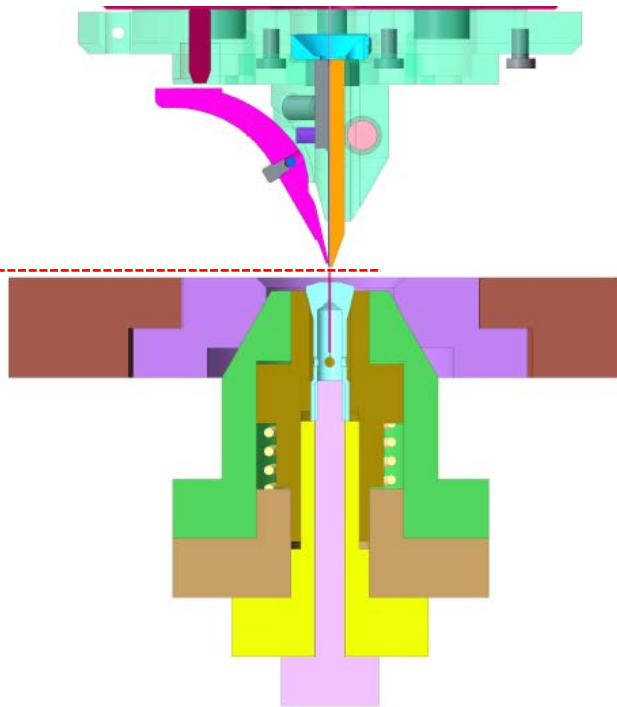
Collet and collet holder build the clamping device which allows to transfer the workpiece to the different process steps.

Clamping device

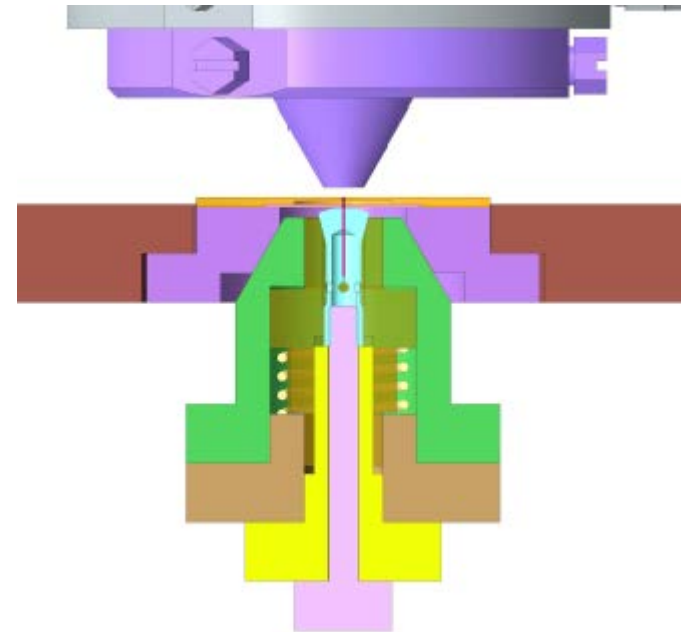
Machine Concept :

cutting and machining station

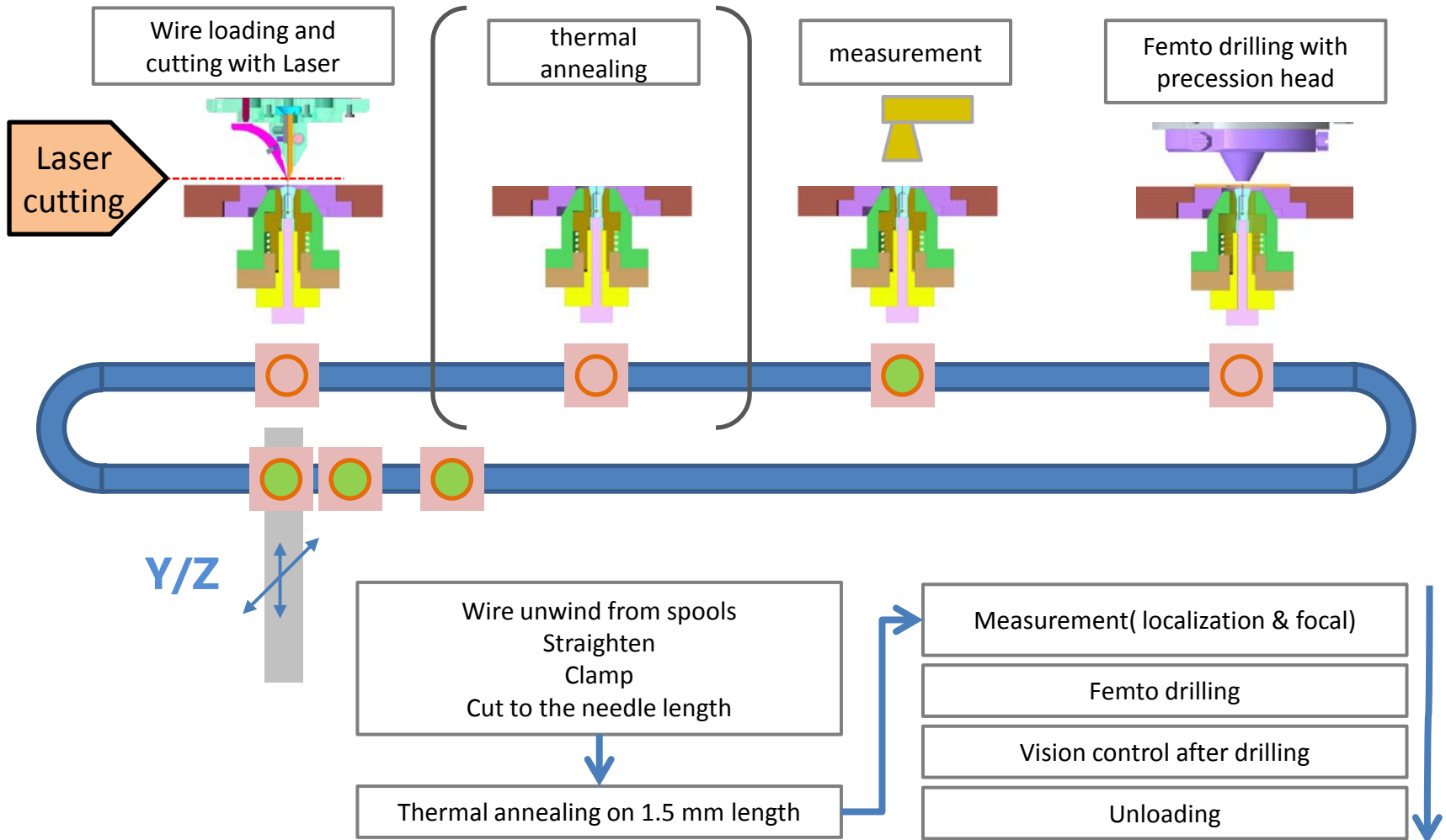
Wire loading
& cutting station



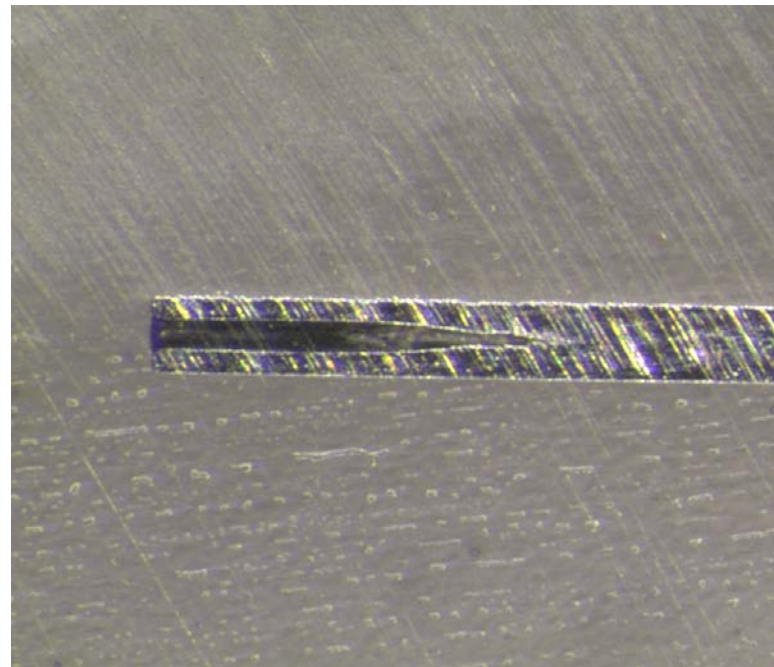
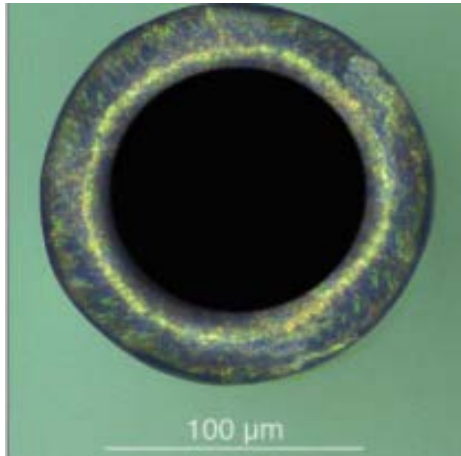
FEMTO drilling



Manufacturing steps



Drilling needle (dia.80 μm)

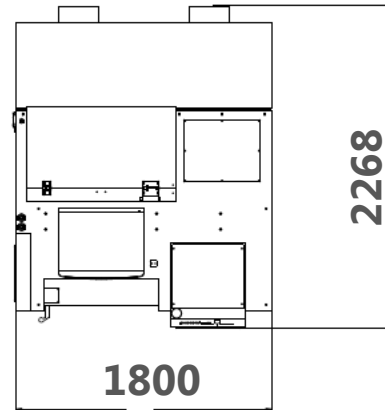
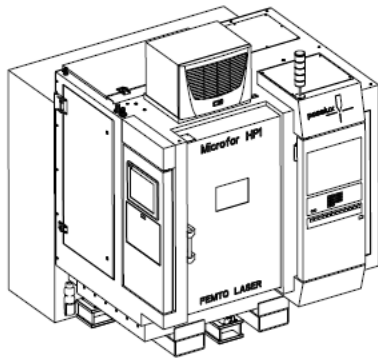
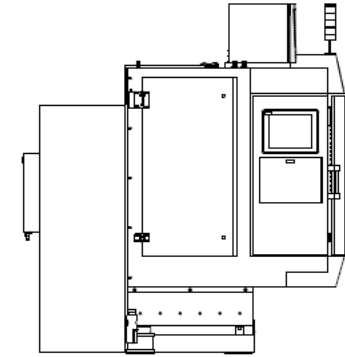
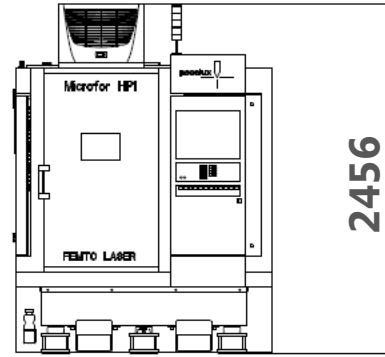
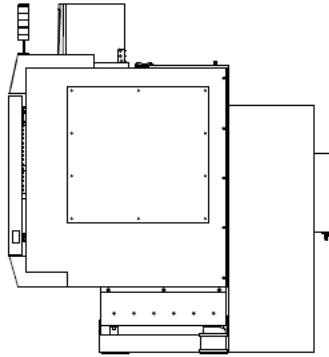


Cycle time

Issue	Value	unit
Process time	5	Sec
Loading / unloading	2	Sec
Total cycle time	7	Sec
Parts / min	8.14	Pces/min
Parts / hour	488.6	Pces/h
Capacity / year	2'814'171	Pces

Default value	Value
Stations	1
Hours per day	24
O.E.E	95%
Days / year	240

Machine layout



POSALUX FEMTO LASER MACHINE



Conventional Ruby Machining Operations

1



Raw stone sawing



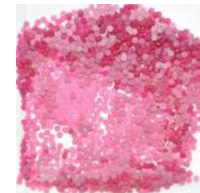
2



Half moon wafer sawing with calibrated thickness



3



Small pads sawing

4



Pre-hole drilling with fiber laser



5



I.D. enlarging



6



O.D. turning

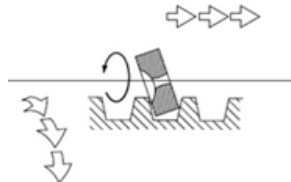
7



Recess machining



8



Olive cut machining



9



Final faces polishing

Femto Laser Ruby Machining Operations

1



Raw stone sawing

2

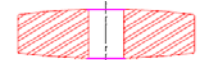


Half moon wafer sawing with calibrated thickness

3



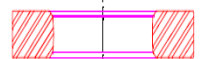
I.D machining



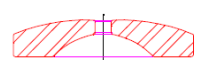
Recess machining



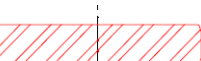
Olive cut machining



Dome shape machining



O.D. machining

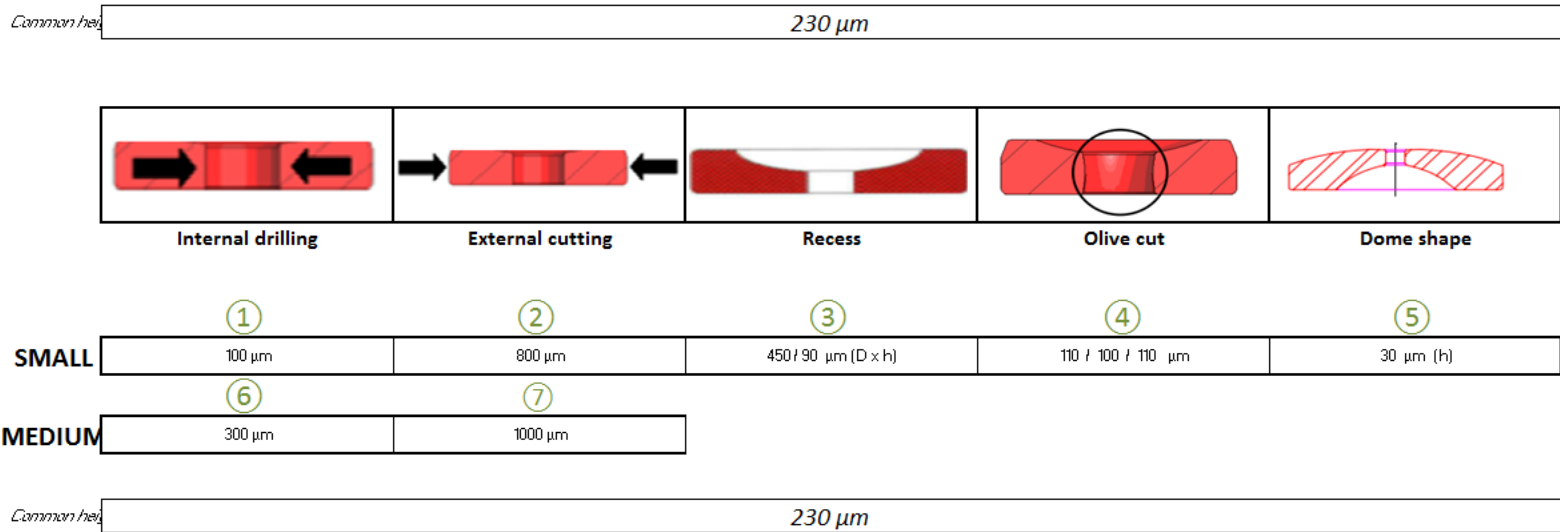


4

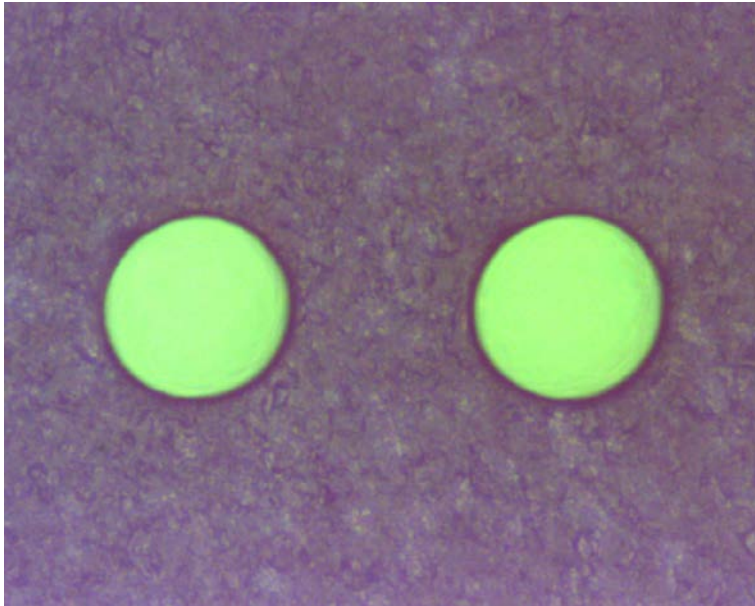


Final faces polishing

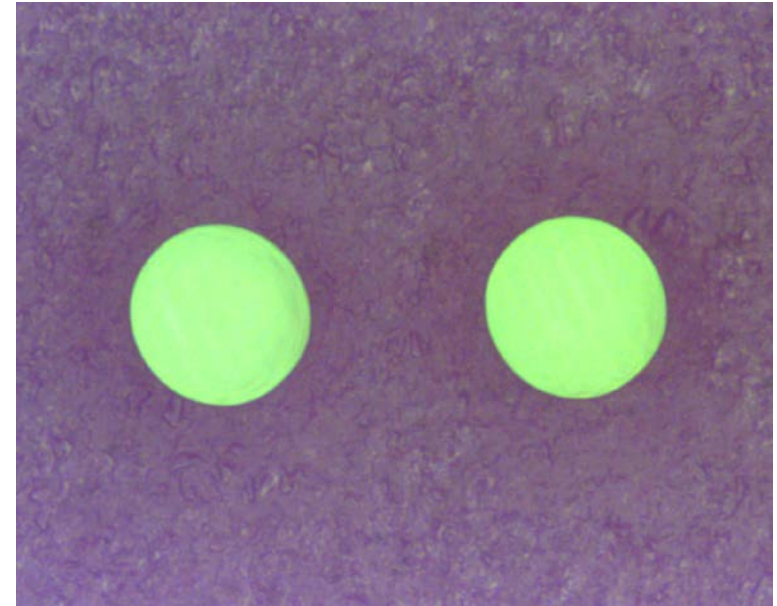
Feasibility issues



Hole diameter 100 μm

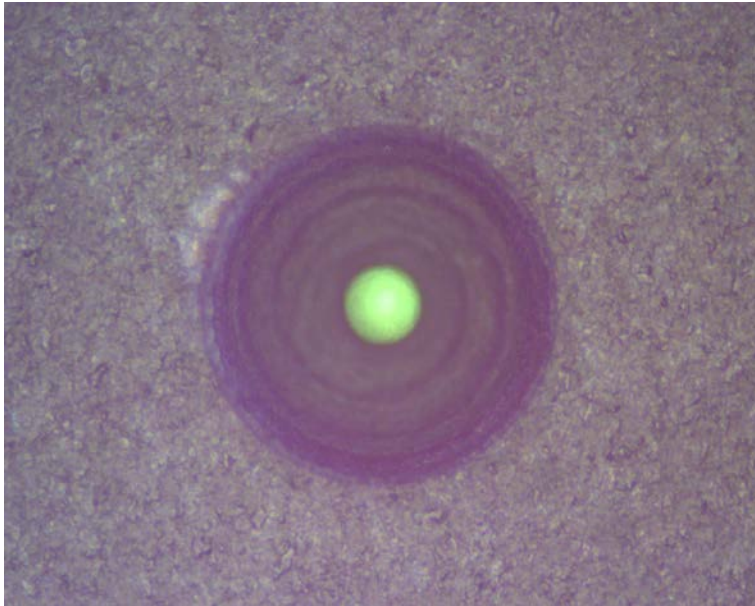


Entry diameter
Dia. 100 μm
Circularity < 2 μm

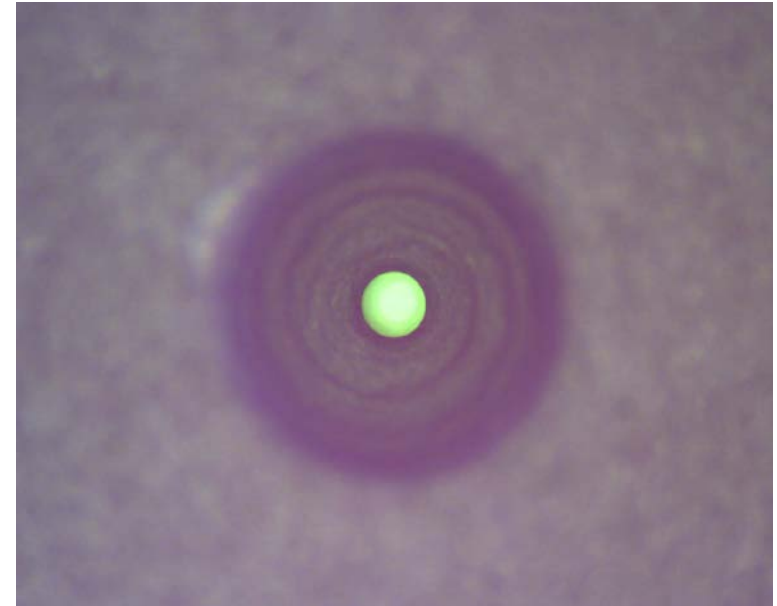


Output diameter
Dia. 100 μm
Circularity < 2 μm

Recess diameter 450 μm x 90 μm (D x h)

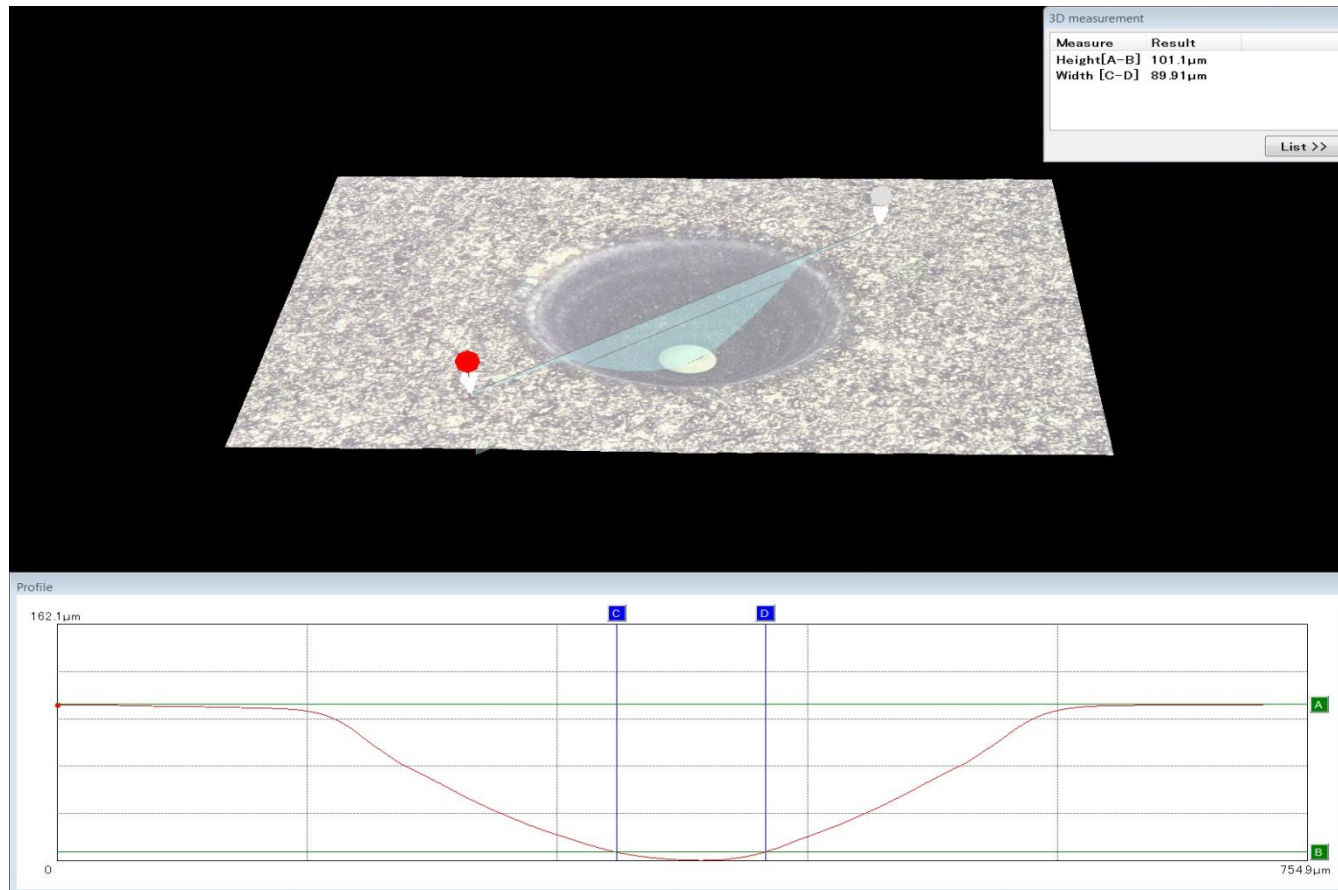


Surface diameter
Dia. 450 μm
Circularity < 5 μm



End recess
Hole entry dia.100 μm

Recess diameter 450 μm x 90 μm (D x h)



Olive cut (footprint Measure)

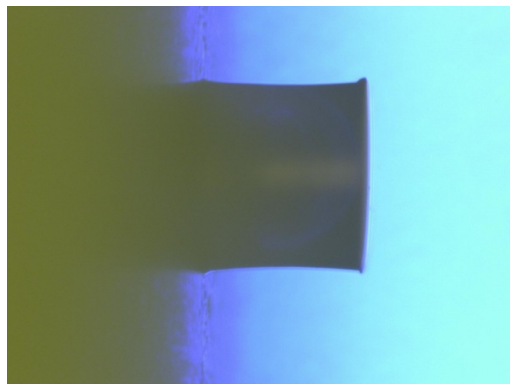


Figure 1: molded prints of shape 1) and 2) of a 300µm hole

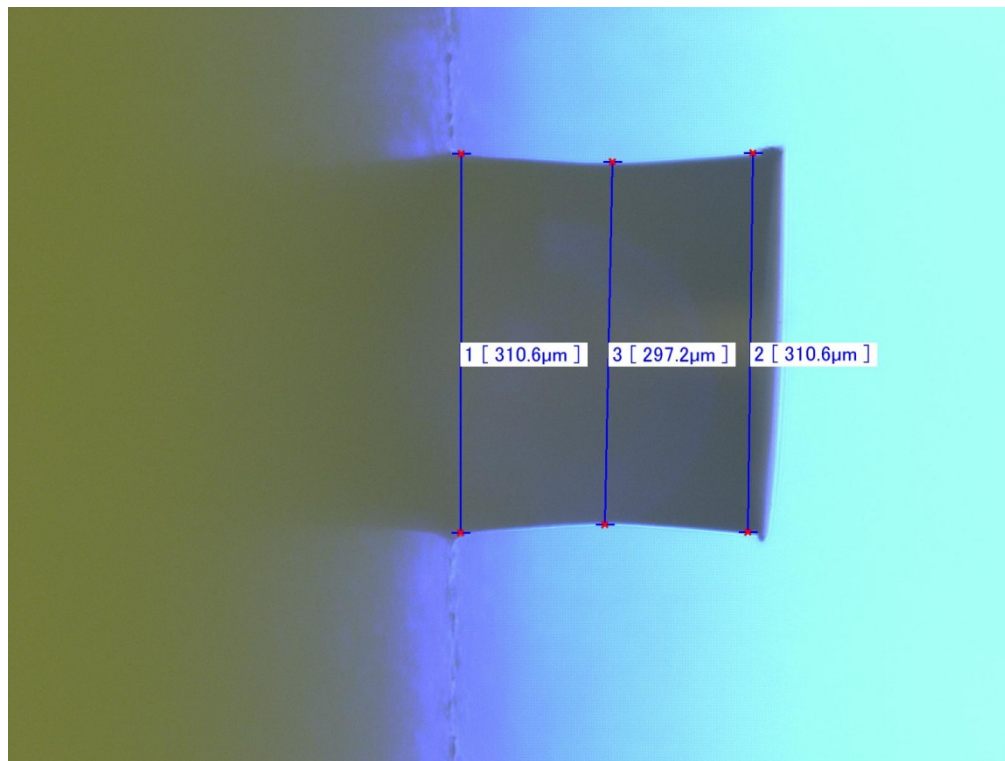
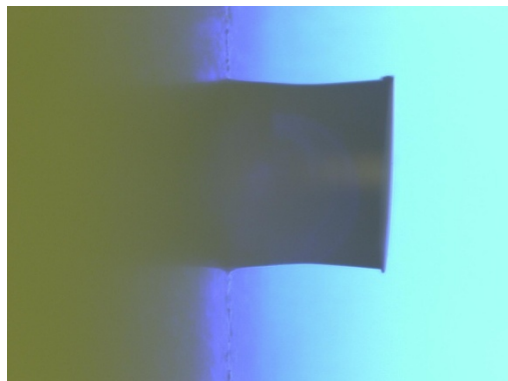
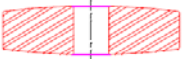
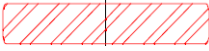
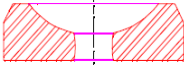
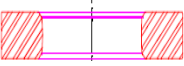
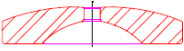


Figure 1: measurement of the molded prints 2)

Ruby Machining Achievement

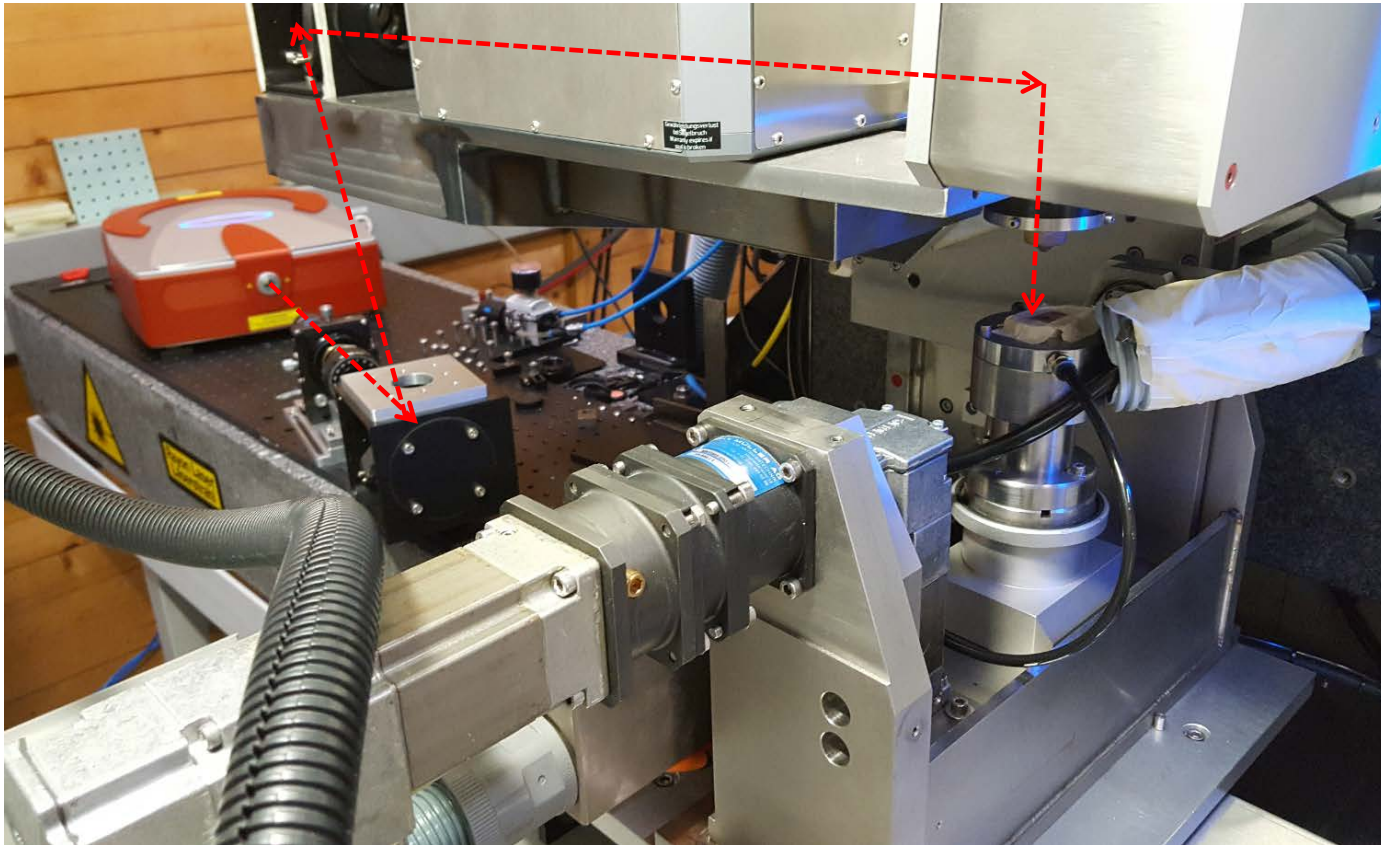
	Operation	Tolerance	Cylindricity	Circularity	Roughness Ra	Concentricity
	I.D. Ø 100µm	± 2 µm	1.5 µm	2 µm	0.1µm	3 µm
	O.D. Ø 800µm	± 2 µm	2 µm	2 µm	0.1µm axial 0.2µm radial	3 µm
	Recess 450 / 90 µm (D x h)	± 5 µm	n/a	5 µm	0.27 µm	3 µm
	Olive cut		n/a	n/a	0.1 µm	n/a
	Dome shape	n/a	n/a	n/a	0.27 µm	n/a

Ruby Machining Cycle Time

Operation	Cycle Time (sec)
I.D. Ø 100µm	2
O.D. Ø 800µm	5.4
Recess 450 / 90 µm (D x h)	2.1
Olive cut of Ø 100µm (include in I.D)	1
Dome shape	6.5

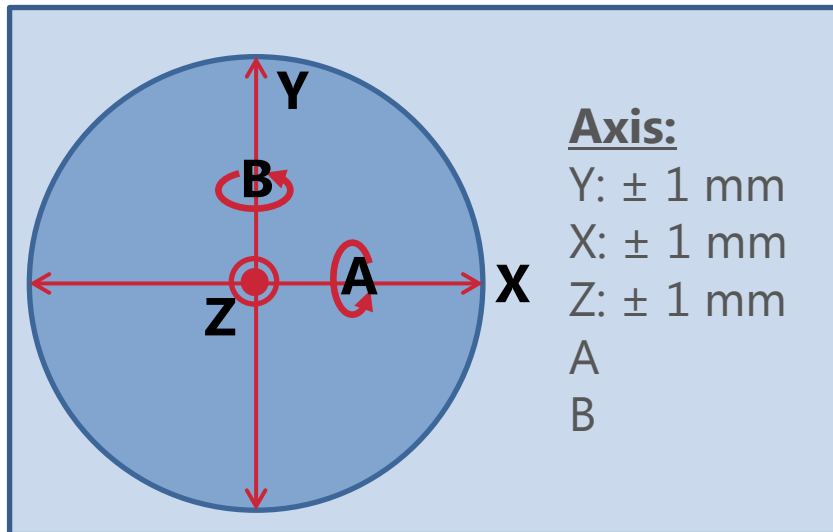
Cutting : precession and axis machine interpolation

5 Axis machine



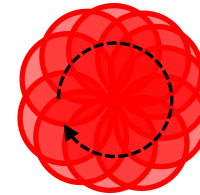
Cinematic:

« precession head and machine »

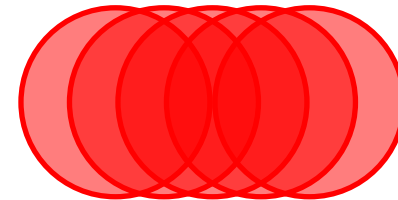


Machine Cinematic: Axis X And Y

1. **Beam spot laser describe a cylindrical trajectory** $r=15 \mu\text{m}$, $\varnothing= 25 \mu\text{m}$, 500 Hz



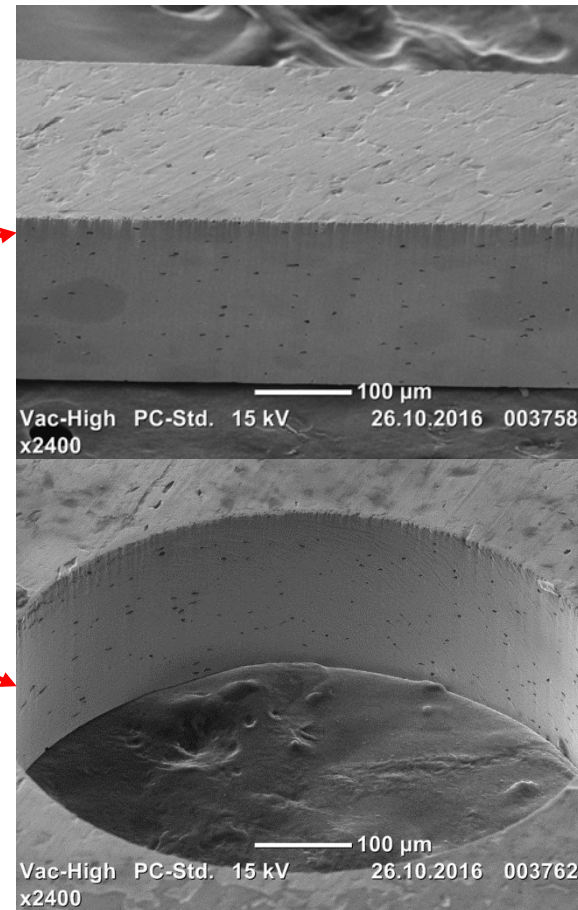
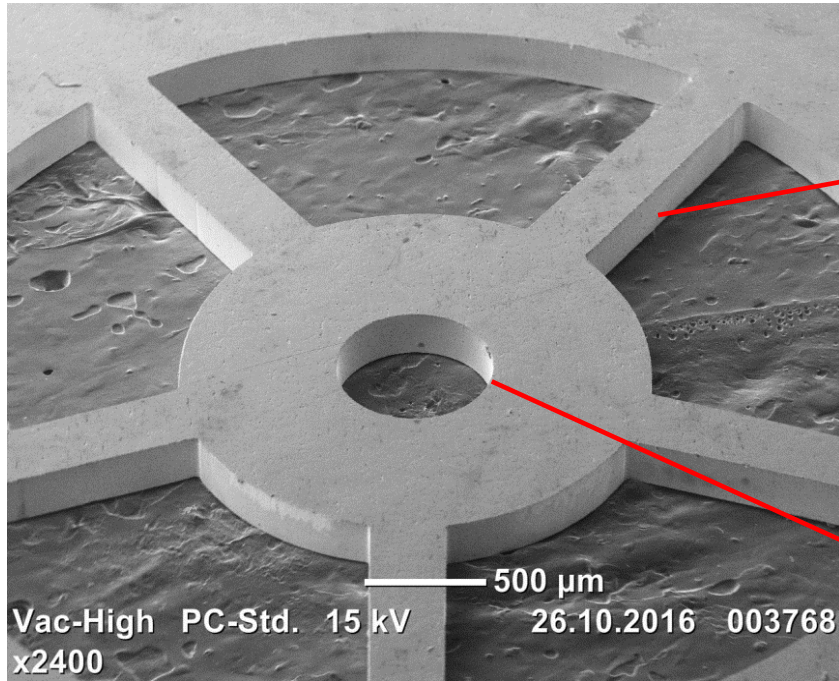
2. **Movement axis combination to obtain a straight line**



3. **Square Clearance correction with laser beam tilting**

Cutting

Brass and Maillechort



Material: Maillechort, Brass

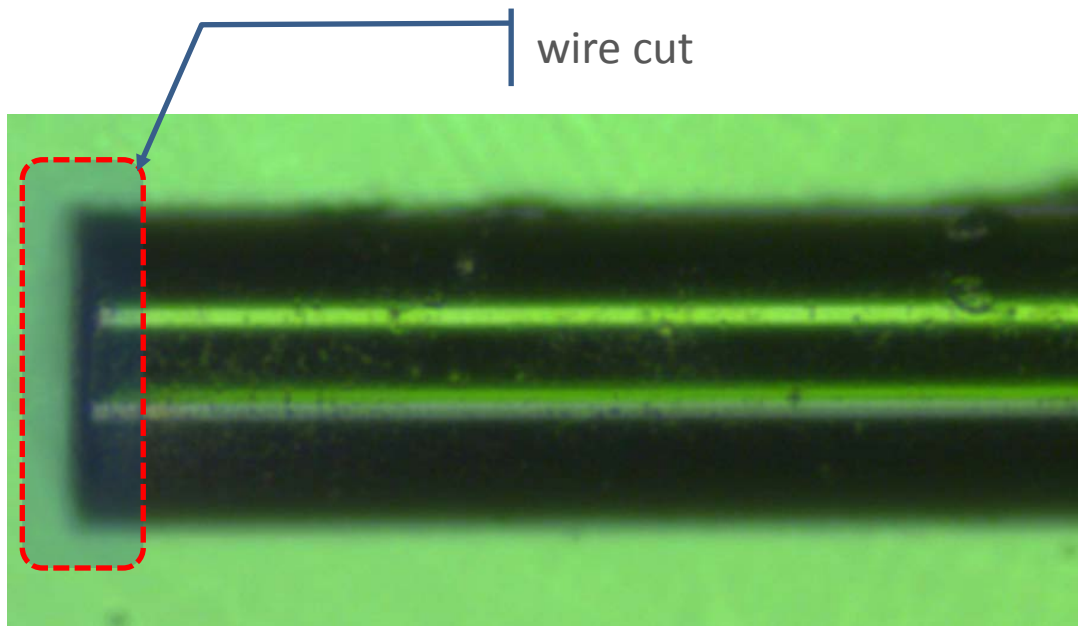
	Tolerance	Cylindricity	Circularity	Roughness	Concentricity	Orth. clearance
Drilling hole \varnothing 700 μm :	$\pm 2 \mu\text{m}$	1.5 μm	2 μm	0.1 μm	< 2 μm	<0.25°
OD cutting \varnothing 6000 μm :	$\pm 2 \mu\text{m}$	2 μm	2 μm	0.1 μm	< 2 μm	<0.5°

FTO (Femto Turning Outside): : Laser cutting of BEAM

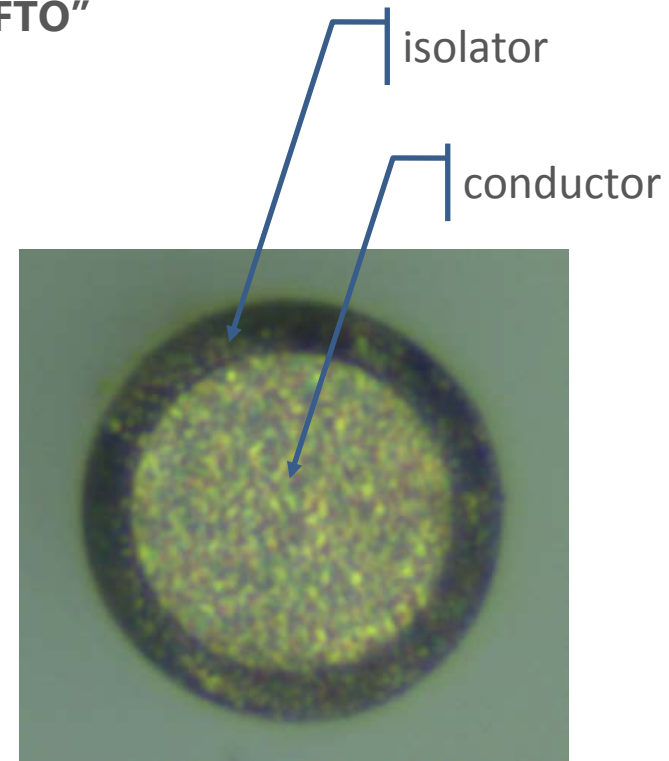
Picture n°3 is a zoom on the cut area of the wire and picture n°4 shows the front view of the cut.

We can notice that the isolator and the conductor are in one layer

⇒ promising base for OD Femto Turning Operation **"OD-FTO"**

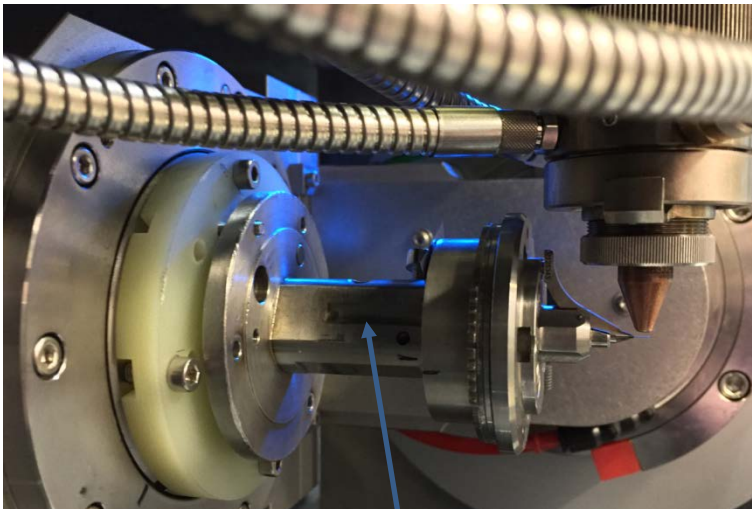


picture n°3



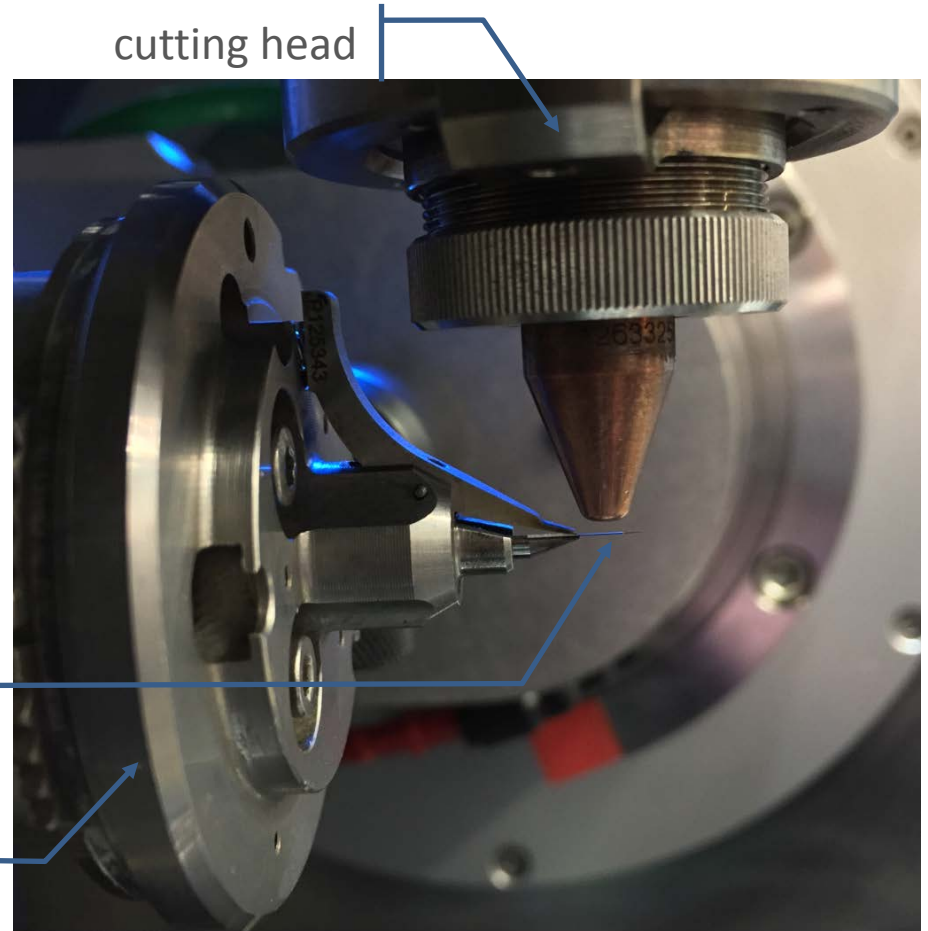
picture n°4

Picture 10 and 11 show the BEAM in current machining position.



picture n°10

Machine C axis

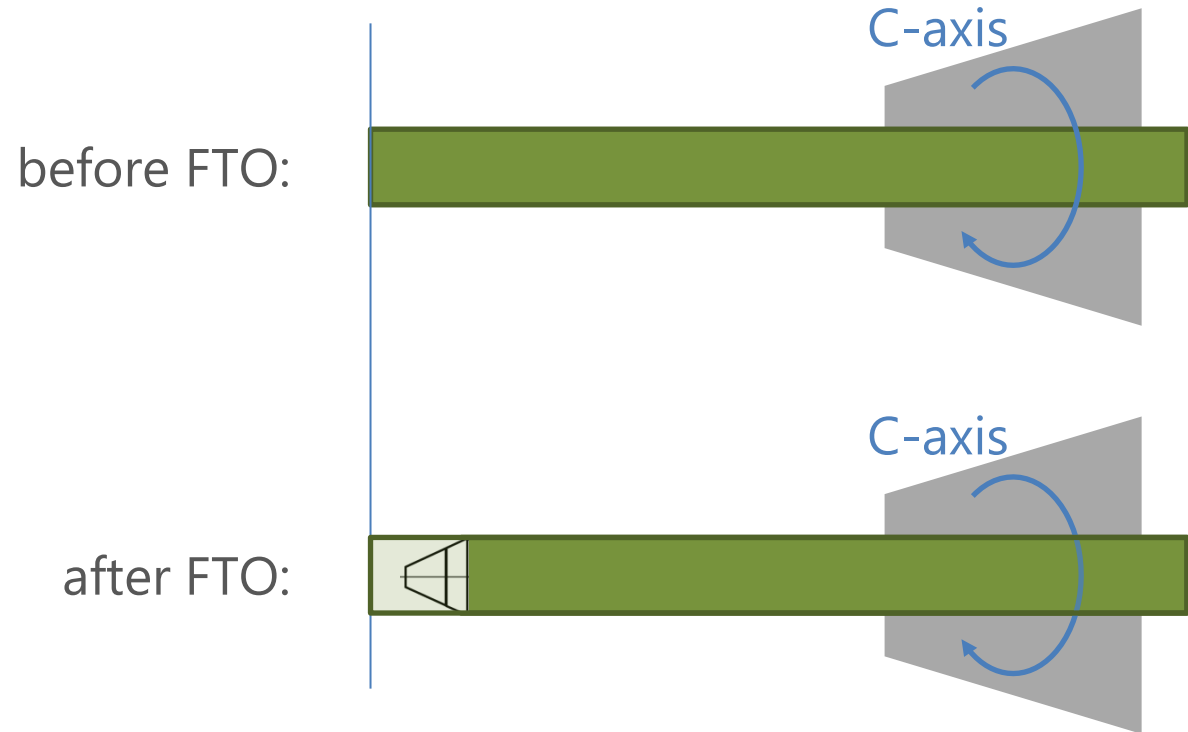


cutting head

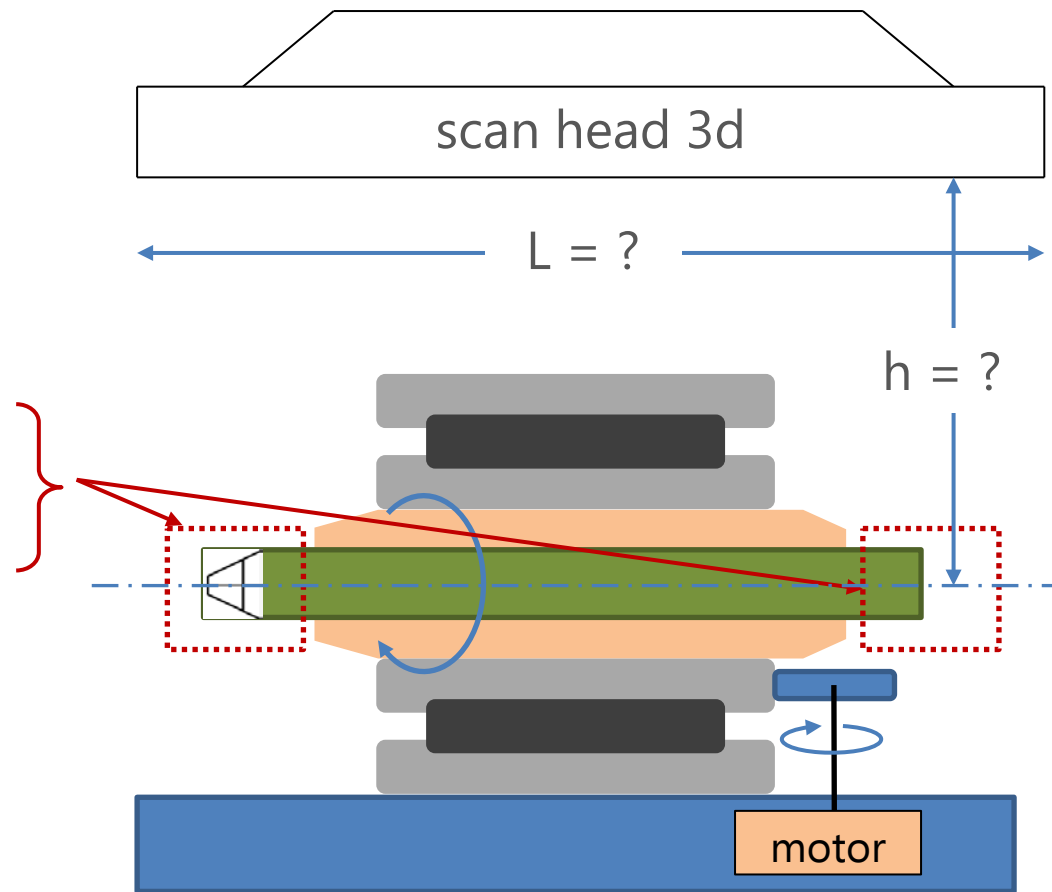
BEAM 3.0 mil

EDM head

picture n°11



Every beam type has to be machined on both ends.
The industrial process is supposed to put in rotation the BEAM with machining access.

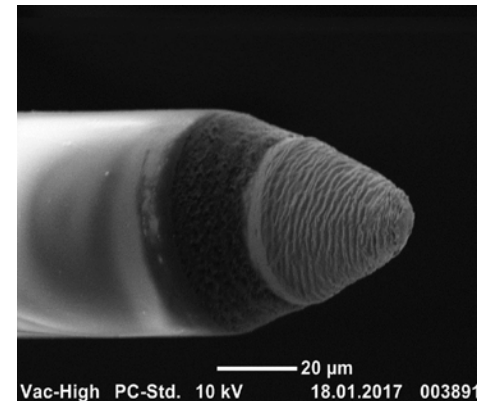
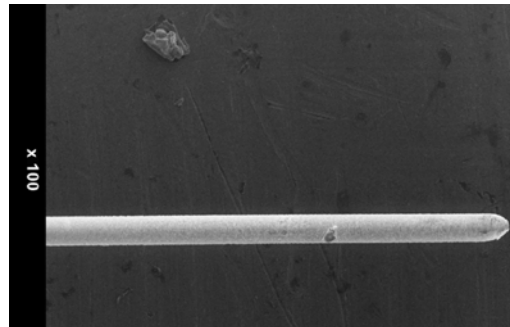


The BEAM length is between:

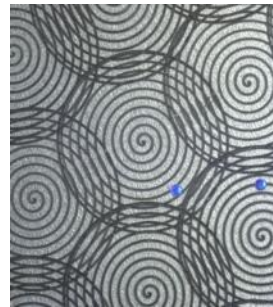
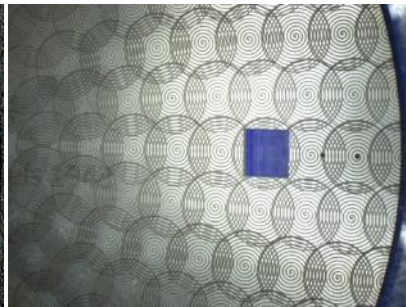
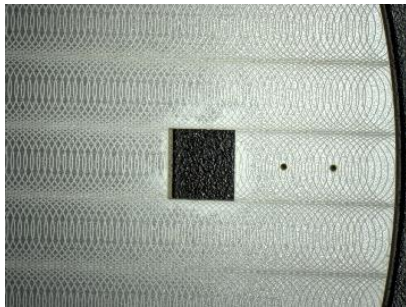
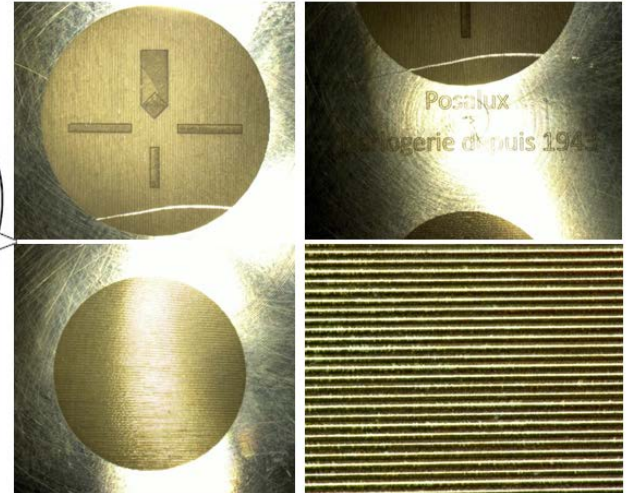
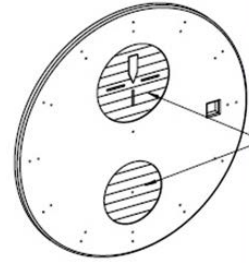
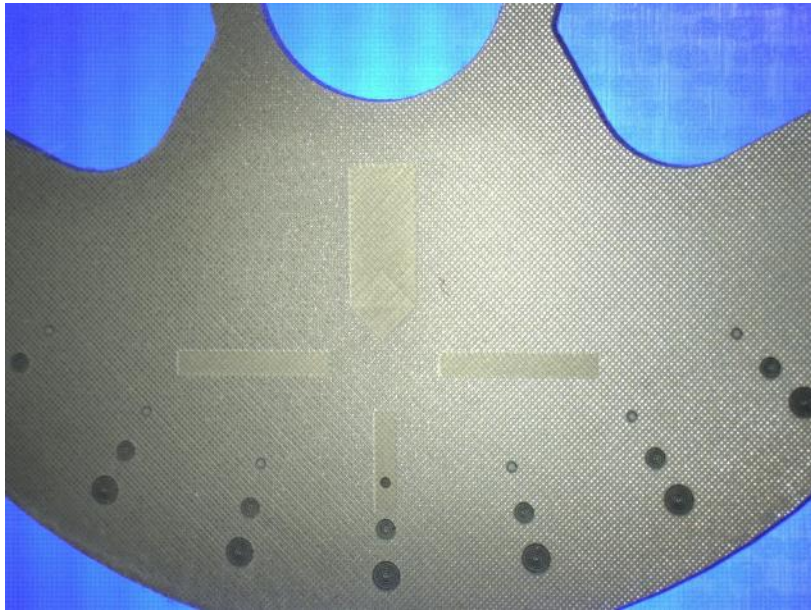
$$6.015 \pm 0.015 \text{ mm (1.6 mil)} \leq \mathbf{L} \leq 11.185 \pm 0.010 \text{ mm (3.0 mil)}$$

Femto Turning Outside process

- ✓ Diameter achieved : 50 μ
- ✓ Tolerances achievement +/- 3 μ



Machining - Engraving – Texturation



Achieved challenges for Femto technology

Roundness	→ < 1.5 μm	✓
Cylindricity / Straightness	→ < 1.5 μm / for all ratio	✓
Entrance / Output shapes	→ Sharpe Edge, Controlled radius	✓
Positive Taper	→ up to +23°	✓
Negative Taper	→ down to -15°	✓
Surface finish	→ < 50 nm	✓
Ratio diam./depth	→ 1:15 (e.g. 30 μm / 450 μm)	✓
Cutting squareness \perp clearance	→ < 0.5°	✓



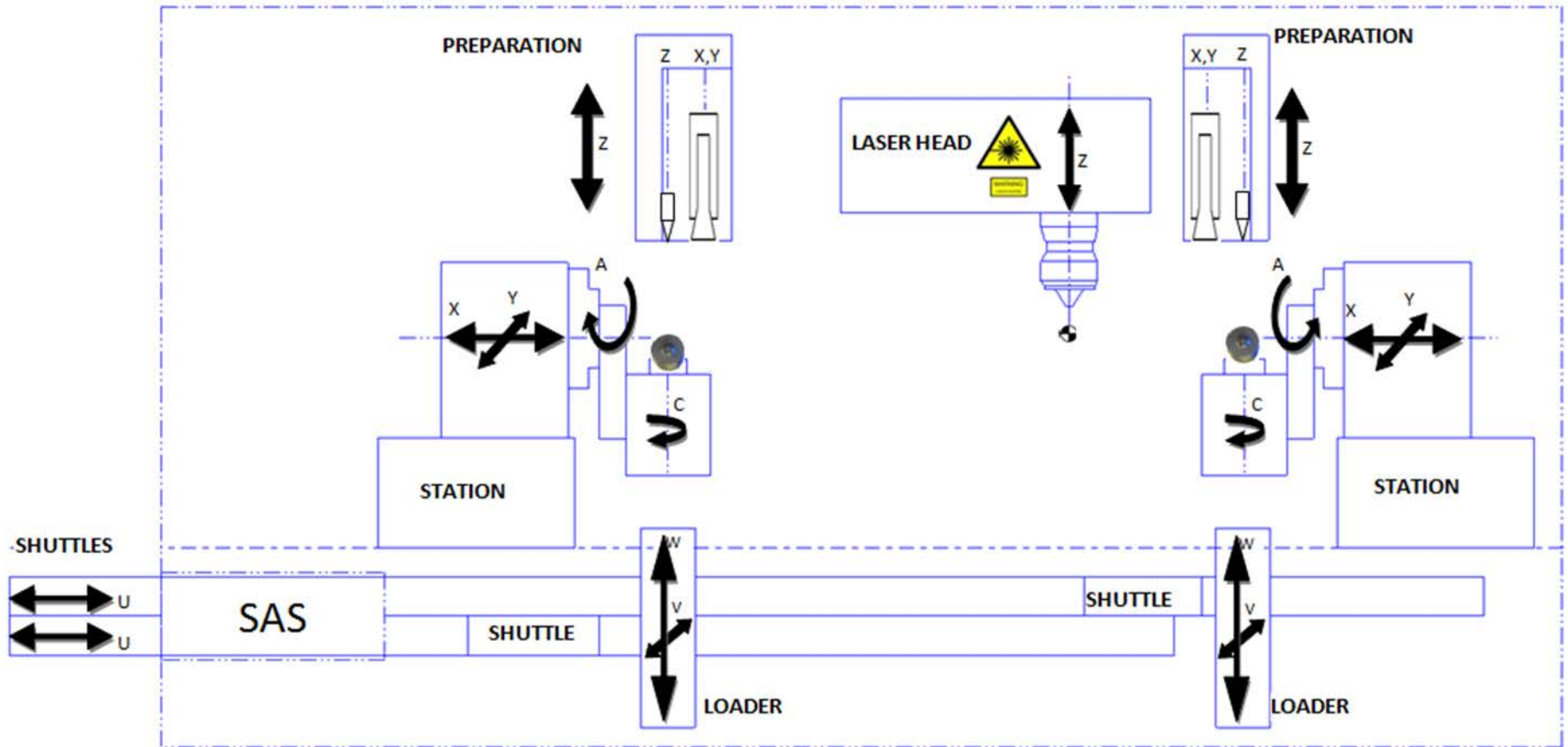
LASER FEMTO Machines



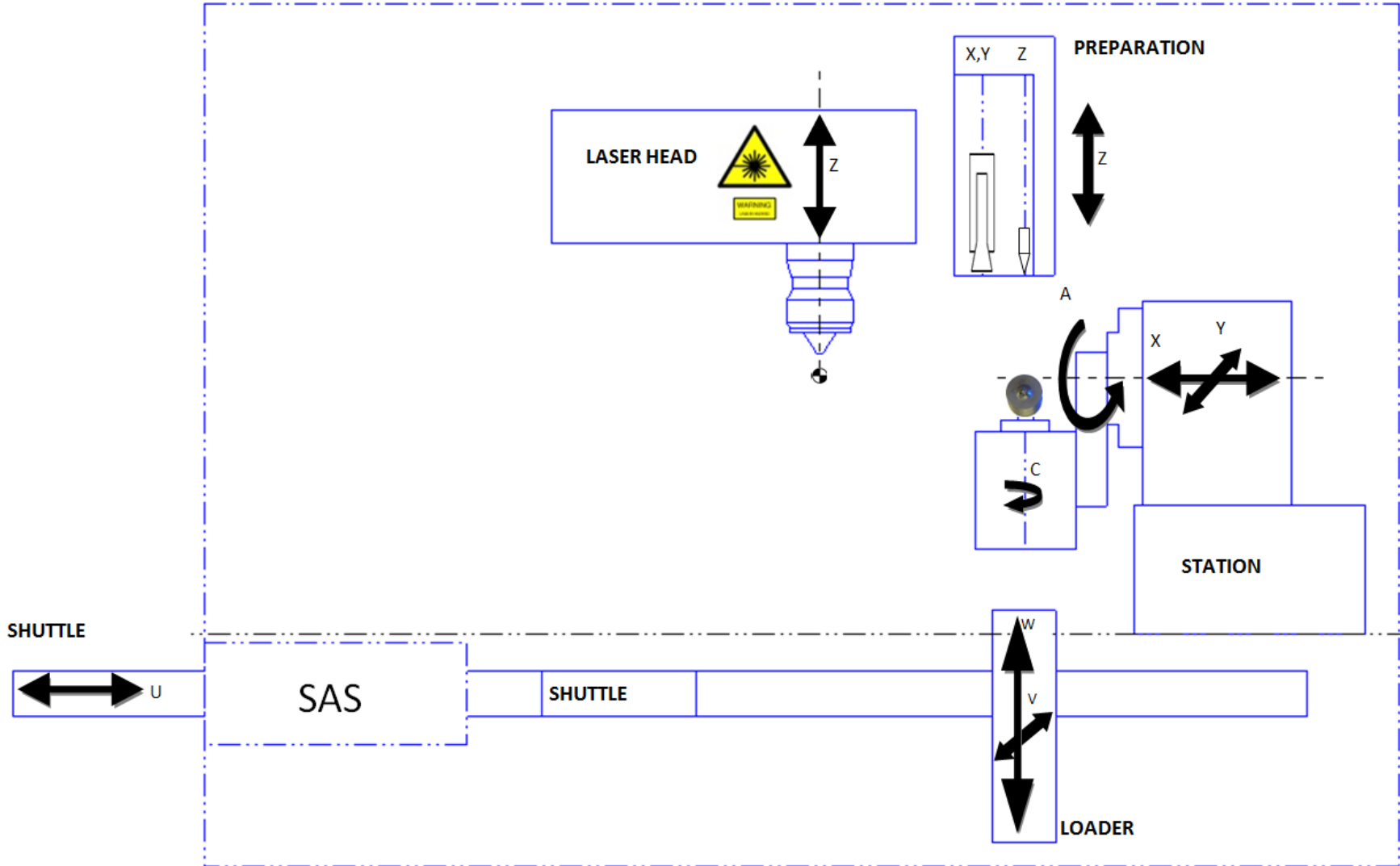
Posalux FEMTO Machines

- Design target = maximize **Laser equipments utilizations**
- High accurate and repeatable **5 axis cinematic**
- **High stability**, insensitive to outside vibrations, temperatures, air quality, thanks Granit base (8 tons), temperature control @+/- 1°C, overpressure in process area, air filtration for optics in 4 stages (class 1)...
- **Posalux software** design to save all milliseconds
- Big effort for **maintenances** / settings **accessibility**
- Full **automation**

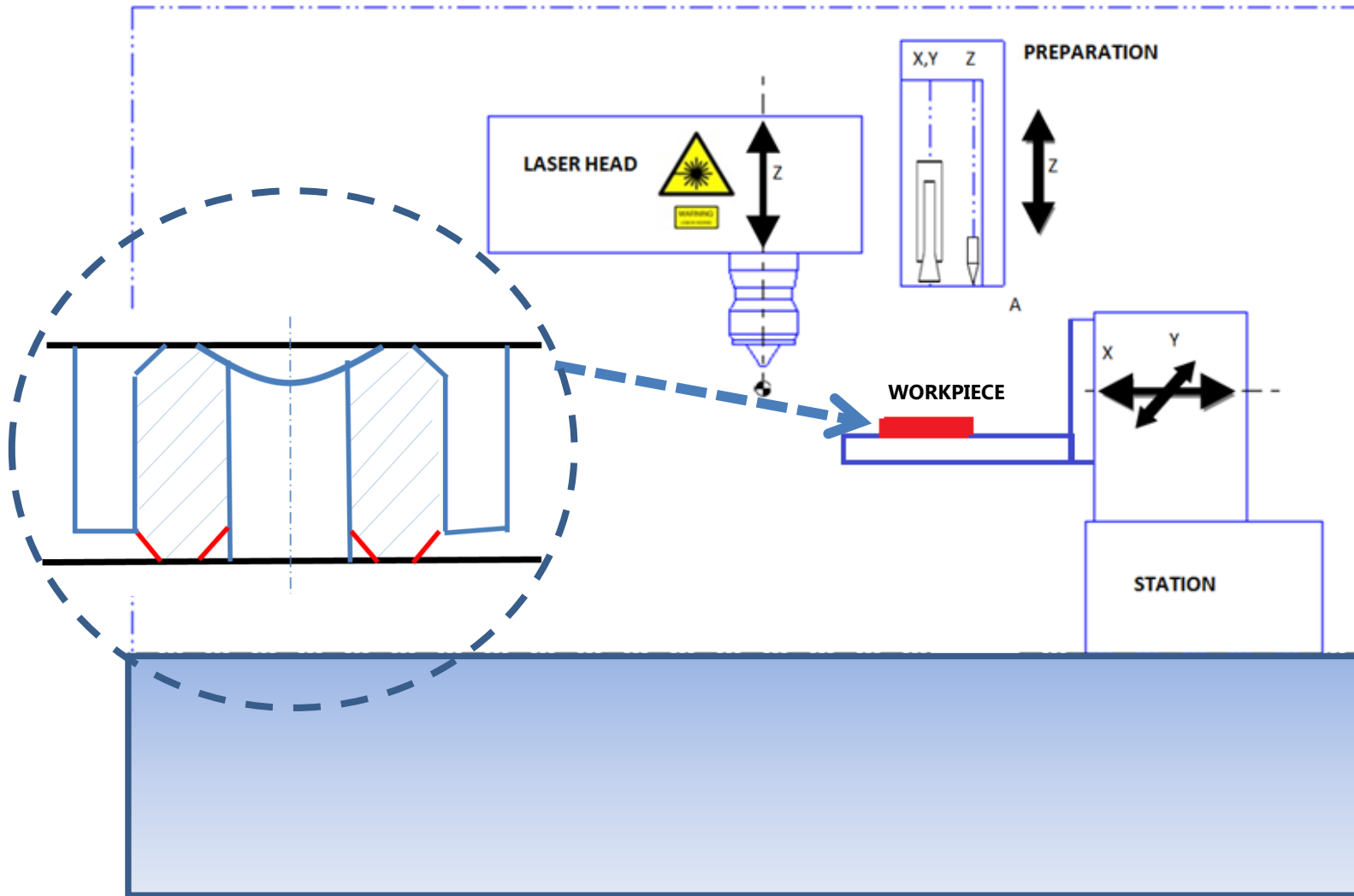
Posalux Femto Twin (standard)



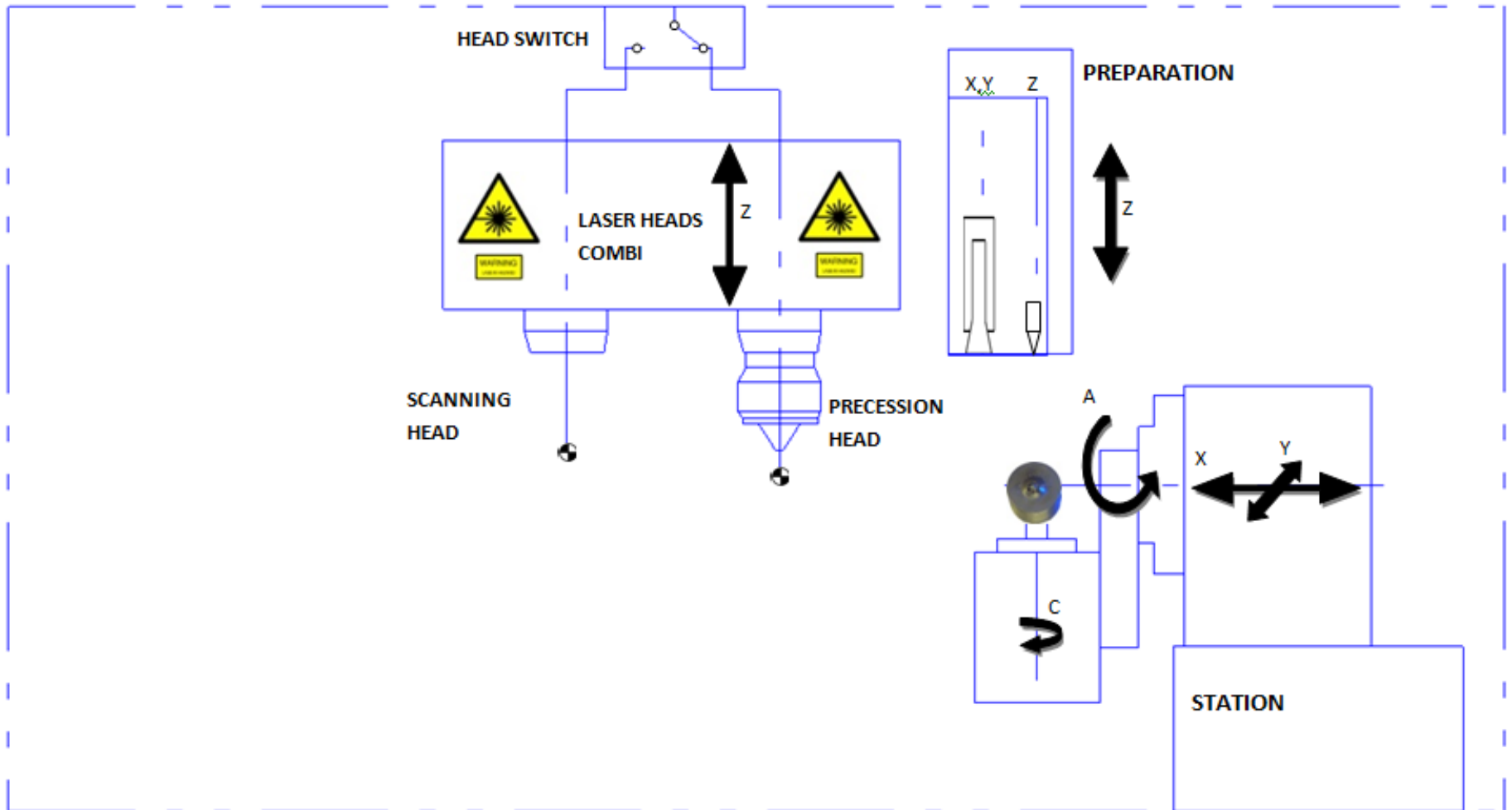
Posalux Femto Mono



Layout Femto Laser Mono - Ruby Application



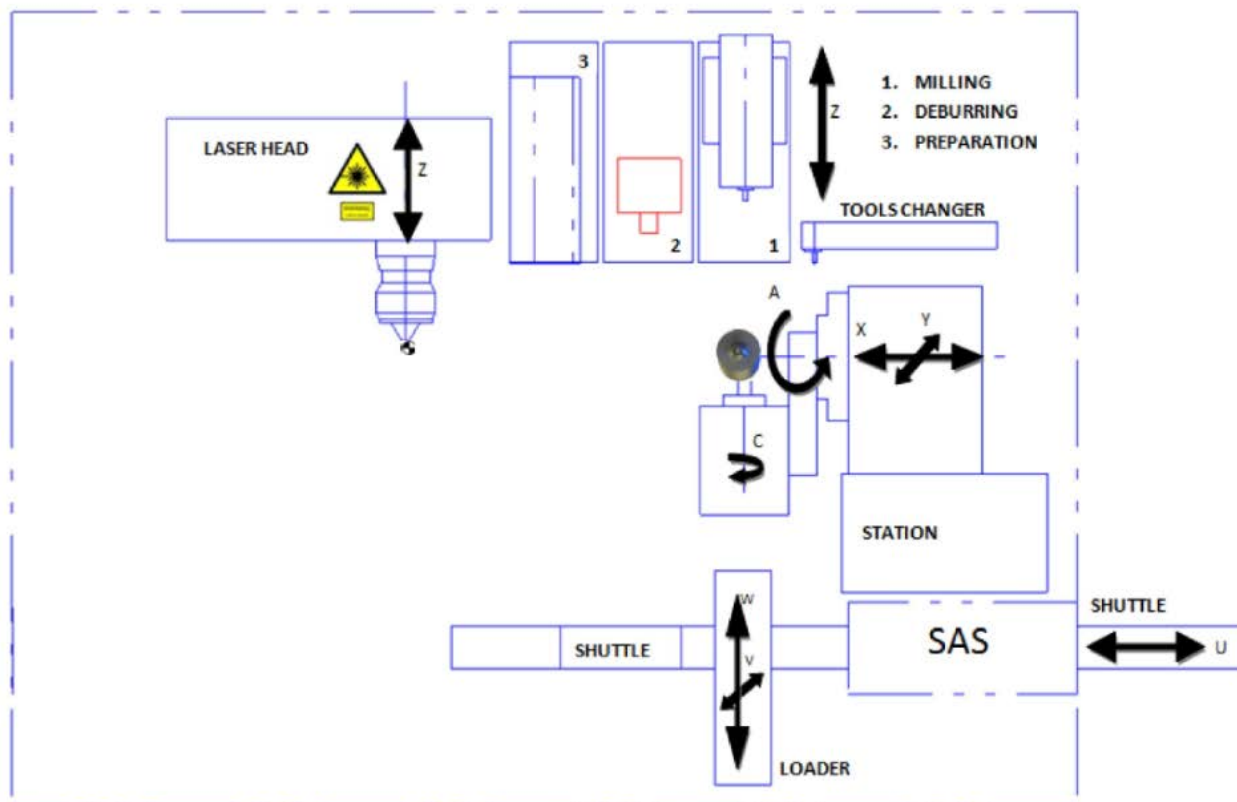
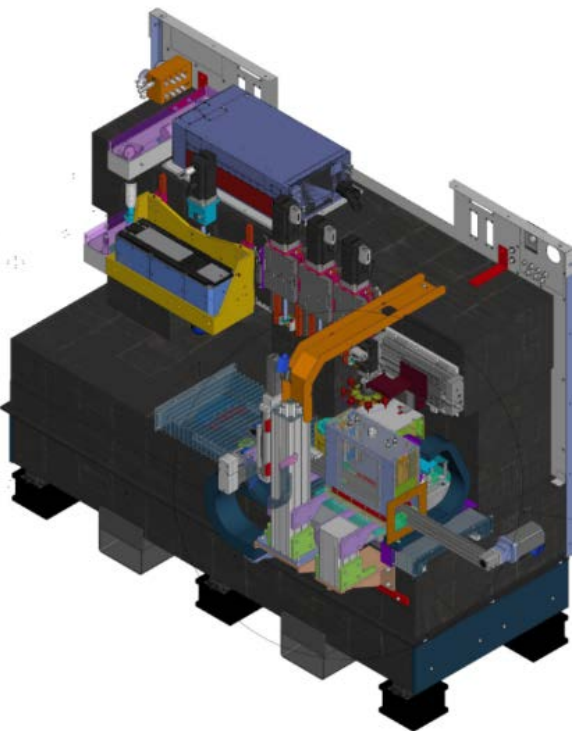
Posalux Femto Mono Combi



Concept Femto Mono Combi 2

Designed for Milling, Deburring and Femto-Drilling

MICROFOR HP1 FEMTO LASER MONO COMBI



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